ULVAC, Inc.

Business Results For FY2025/6

Consolidated Financial Results and Earnings Forecast
New Mid- to Long-Term Management Plan（Value Up Plan)

Aug. 13, 2025

Disclaimer regarding forward-looking statements etc.

- **Forward-looking statements**
  Forward-looking statements of the company in this presentation are based on information that was available at the time these documents were prepared. There are several factors that directly or indirectly impact the company performance, such as the global economy; market conditions for FPDs, semiconductor, electronic devices, and raw Materials; trends in capital expenditures and fluctuations in exchange rates. Please note that actual business results may differ significantly from these forecasts and future projections.
- **Processing of numbers**
  Figures and percentages in this document have been rounded to the nearest unit.
- **Product Category Change**
  From FY25/6, the name of “FPD production equipment” has been changed to “Display and Energy-Related Production Equipment”.

ULVAC

Summary

Consolidated Financial Results for the Fiscal Year Ending June 2025

- Net sales and all profit items mostly have come in line with the previous forecasts.
  Gross profit margin reached 31.8%, the highest level since the company's listing.
- From the perspective of stable dividends with a focus on shareholder returns, **the dividend will be maintained at the previously forecasted ¥164, marking a record high.**

Forecast for FY26/6

- Orders received are showing a recovery trend. Sales growth centered on the semiconductor electronics field is expected to maintain a high level comparable to FY25/6.
- All profit items are expected to improve steadily.

New Mid- to Long-Term Management Plan (Value-Up Plan)

- We are **implementing a fundamental reform** to optimize management resources and review the business portfolio centered on semiconductor electronics, aiming to ensure sustainable high growth and high profitability.

The new **Mid- to Long-Term Management Plan, "Value-Up Plan",** starts from FY26/6.

Consolidated Financial Results for FY2025/6

Earnings Forecast for FY2026/6

New Mid-Long-Term Management Plan
～ Value Up Plan～

- Business Reforms
- Growth Strategy
- Production Reforms
- Capital Allocation

Consolidated Financial Results for FY2025/6

- Net sales and all profit items mostly have come in line with the previous forecasts. The gross profit margin of 31.8% is the highest level since the company's listing.
- The dividend of ¥164 for FY2025/6 is a record high.

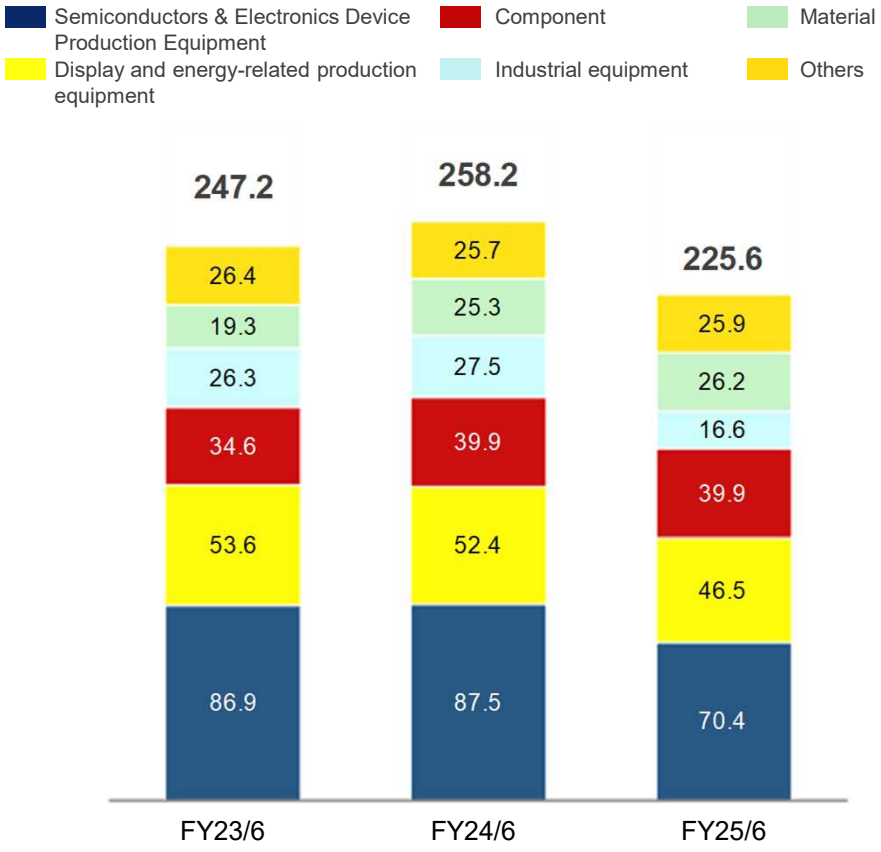
(Unit: ¥1 billion)	FY24/6	FY25/6	YoY		FY25/6 Latest Forecast	Vs.Forecast
			Amount	%		%
Orders Received	**258.2**	**225.6**	**-32.6**	**-13%**	**230.0**	**-2%**
Net Sales	**261.1**	**251.2**	**-9.9**	**-4%**	**250.0**	**+0%**
Gross Profit	**80.7**	**79.9**	**-0.8**	**-1%**	**80.0**	**-0%**
Gross Profit Margin	**30.9%**	**31.8%**	**+0.9pt**	**-**	**32.0%**	**-**
SG&A	**50.9**	**53.3**	**+2.4**	**+5%**	**53.0**	**+1%**
Operating Profit	**29.8**	**26.5**	**-3.2**	**-11%**	**27.0**	**-2%**
Operating Profit Margin	**11.4%**	**10.6%**	**-0.8pt**	**-**	**10.8%**	**-**
Profit attributable to owners of parent	**20.2**	**16.7**	**-3.5**	**-18%**	**17.0**	**-2%**
To net sales ratio	**7.7%**	**6.6%**	**-1.1pt**	**-**	**6.8%**	**-**
Dividend per Share (Yen)	**144**	**164**			**164**	

Order and Net Sales Performance

- Orders decreased YoY due to a slowdown in investments in power devices, battery business, etc.
- Net Sales achieved the second-highest level since the company's listing, supported by a high backlog of orders.

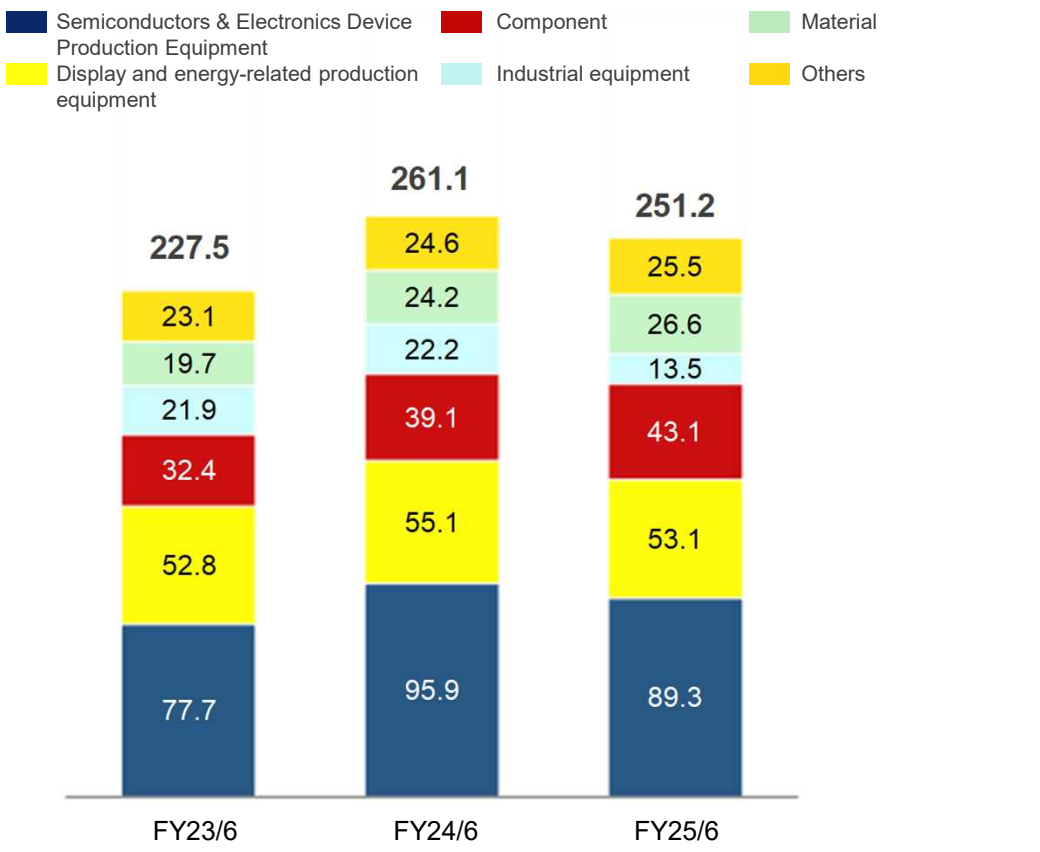
Orders Received

(Unit: ¥1 billion)



Net Sales

(Unit: ¥1 billion)

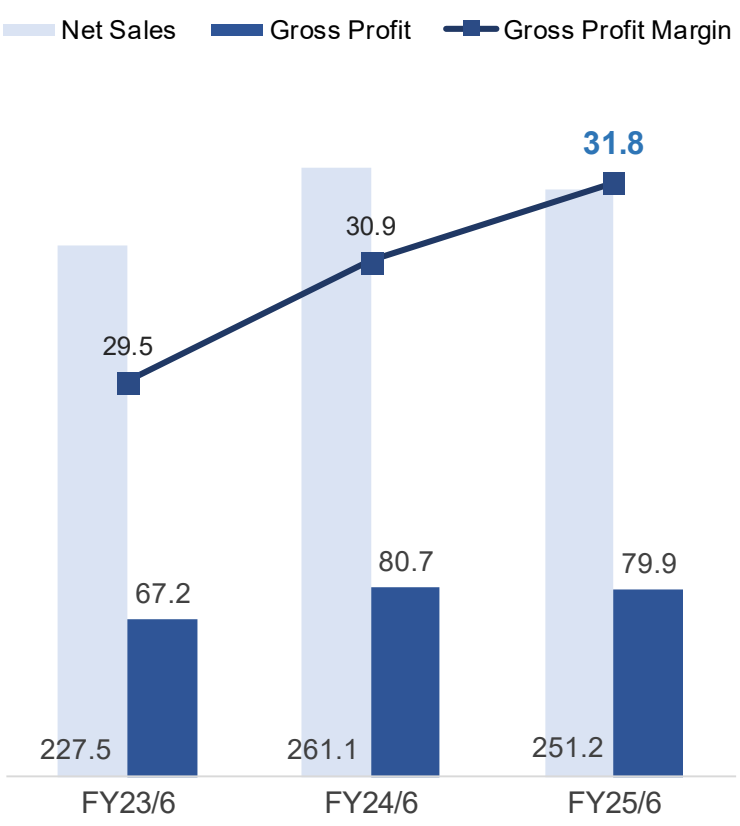


Profit Margin Trends

- Gross Profit Margin reached 31.8%, the highest level since listing, due to improved product mix and contributions from high-margin projects.
- Operating Profit Margin declined YoY due to a decrease in net sales and increased expenses such as research and development expenses.

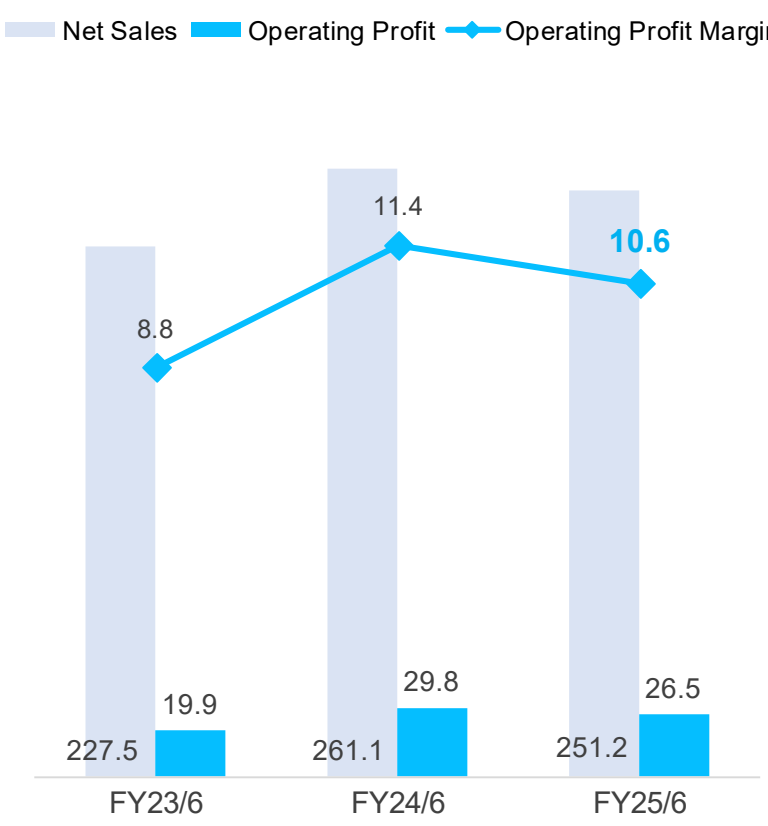
Gross Profit Margin

(Unit: ¥ 1 billion, %)



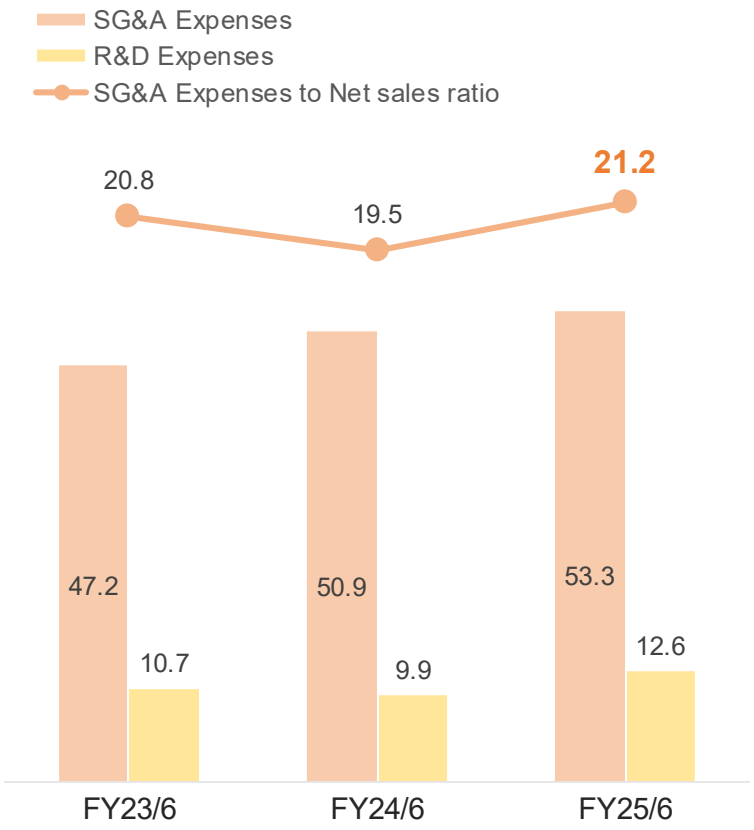
Operating Profit Margin

(Unit: ¥ 1 billion, %)



S.G.&A Expenses

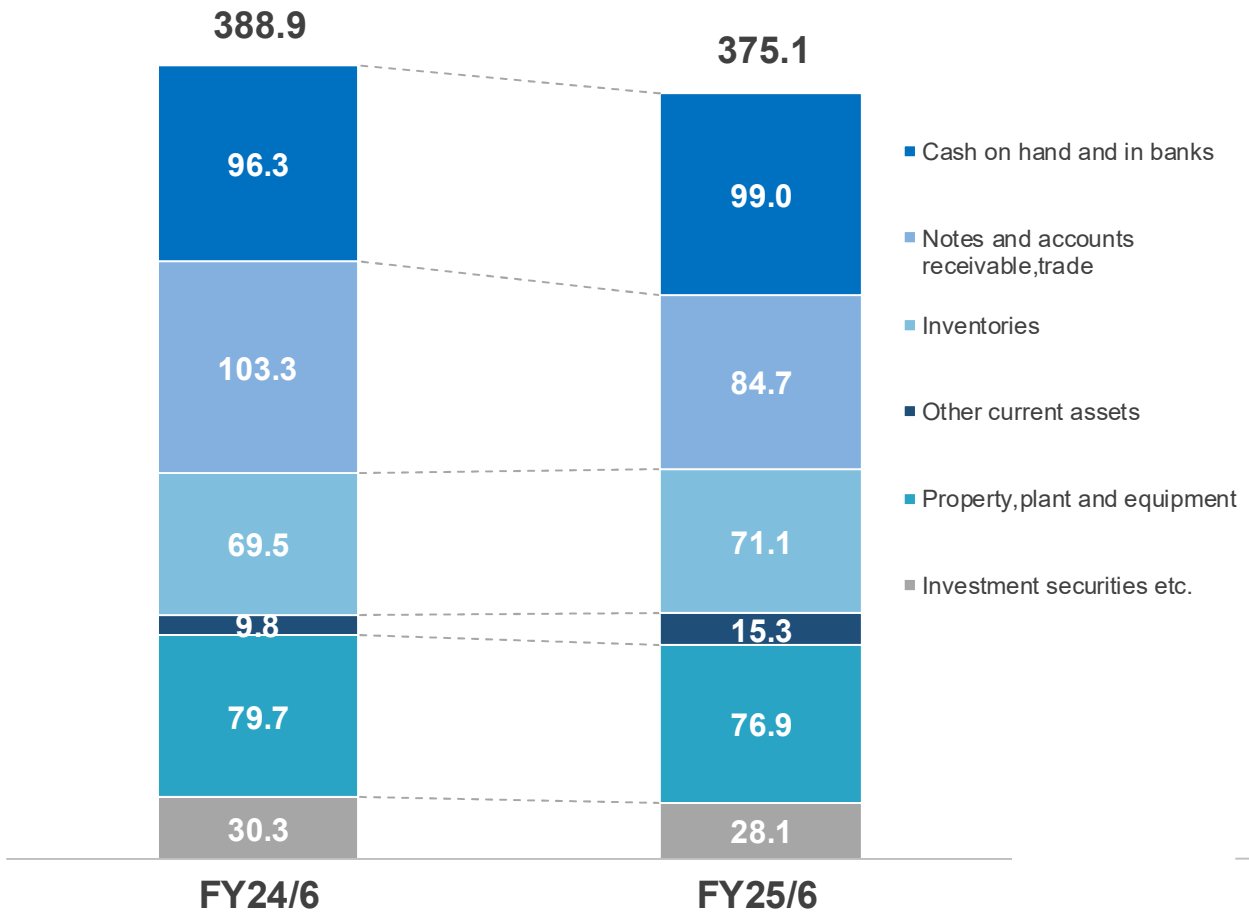
(Unit: ¥ 1 billion, %)



Consolidated Balance Sheet

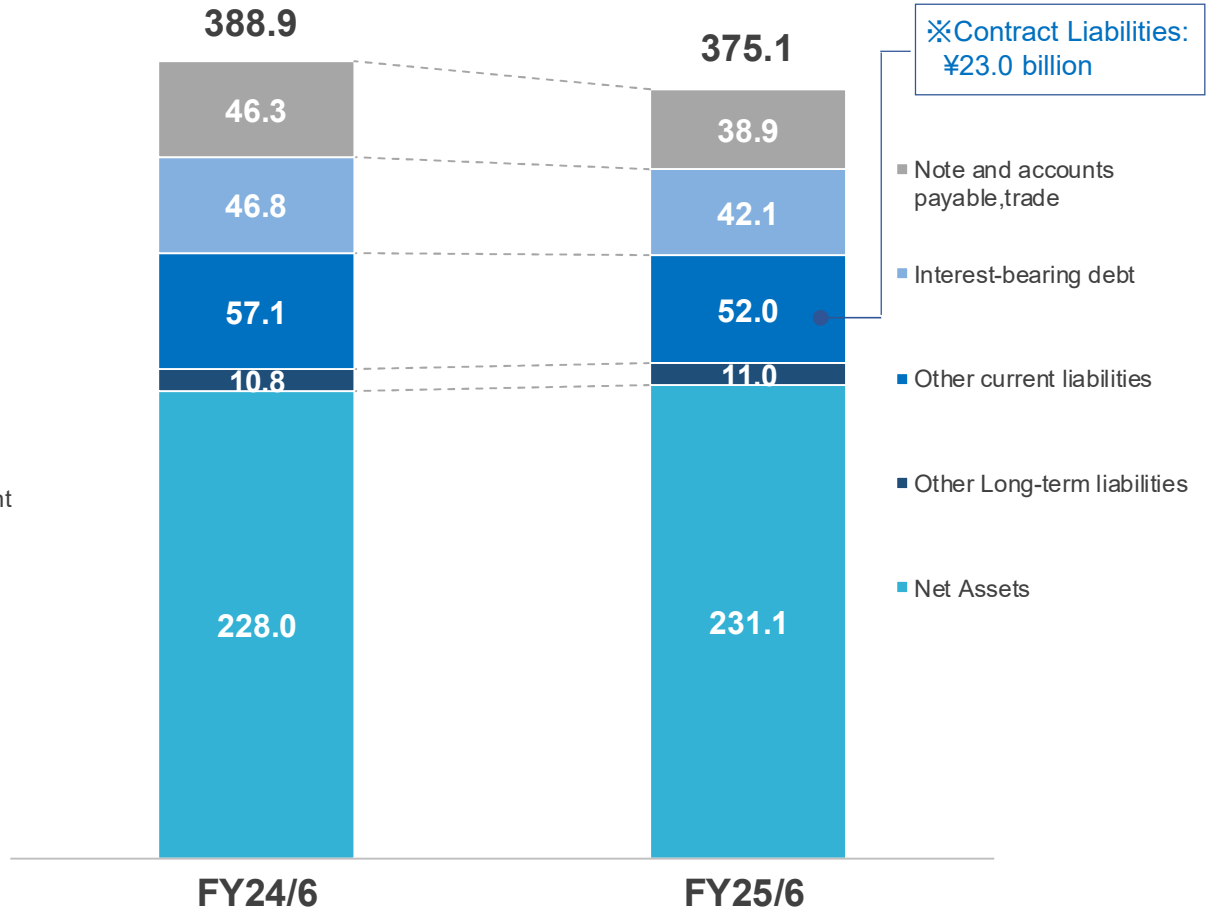
Assets

(Unit: ¥1 billion)



Liabilities and Net Assets

(Unit: ¥1 billion)



Consolidated Financial Results for FY2025/6

Earnings Forecast for FY2026/6

New Mid-Long-Term Management Plan
～ Value Up Plan～

- Business Reforms
- Growth Strategy
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Forecast for FY2026/6

- Orders received are recovering due to continued investments in semiconductor-related business and a rebound in investments in power devices.
- Net sales are expected to remain at a high level supported by order recovery and shortened manufacturing lead time. All profit margins are anticipated to improve steadily .

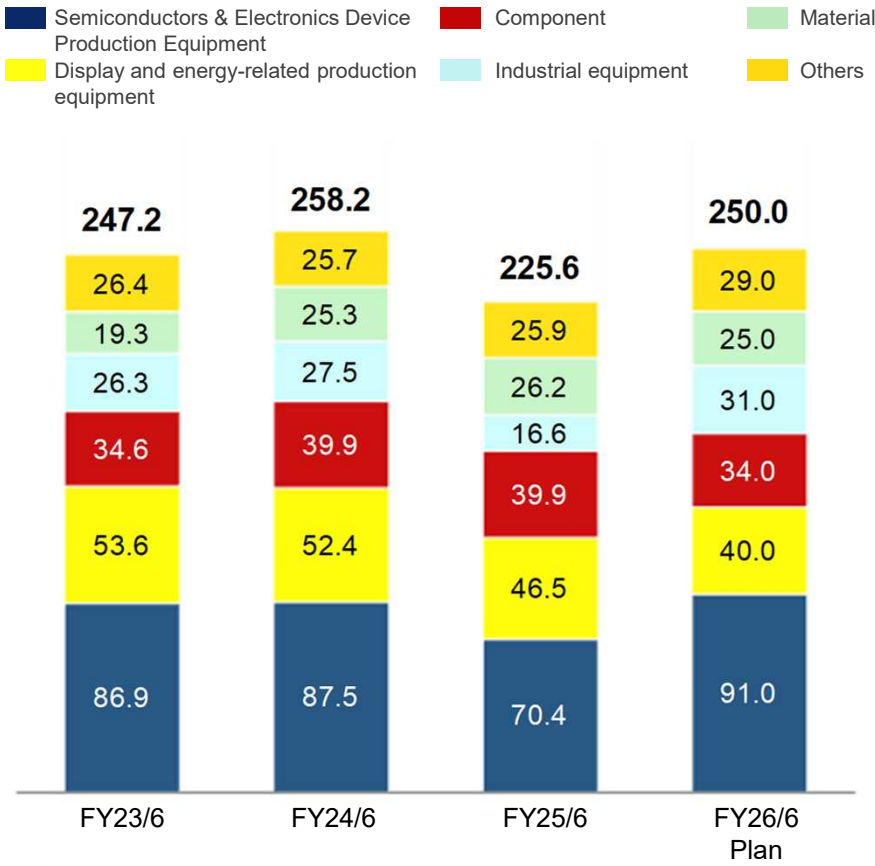
(Unit: ¥1 billion)	FY25/6	FY26/6 Forecast			YoY	
		H1	H2	Full Year	Amount	%
Orders Received	225.6	120.0	130.0	250.0	+24.4	+11%
Net Sales	251.2	115.5	134.5	250.0	-1.2	-0%
Gross Profit	79.9	35.5	47.0	82.5	+2.6	+3%
Gross Profit Margin	31.8%	30.7%	34.9%	33.0%	+1.2pt	-
Operating Profit	26.5	9.0	19.5	28.5	+2.0	+7%
Operating Profit Margin	10.6%	7.8%	14.5%	11.4%	+0.8pt	-
Profit attributable to owners of parent	16.7	6.5	13.5	20.0	+3.3	+20%
To net sales ratio	6.6%	5.6%	10.0%	8.0%	+1.4pt	-

Orders and Net Sales Plan (FY2026/6)

- Orders received are recovering due to continued investments in Semiconductors and Electronics and investment recovery in Power Devices.
- Net sales are expected to remain at a high level supported by order recovery and shortened manufacturing lead time.

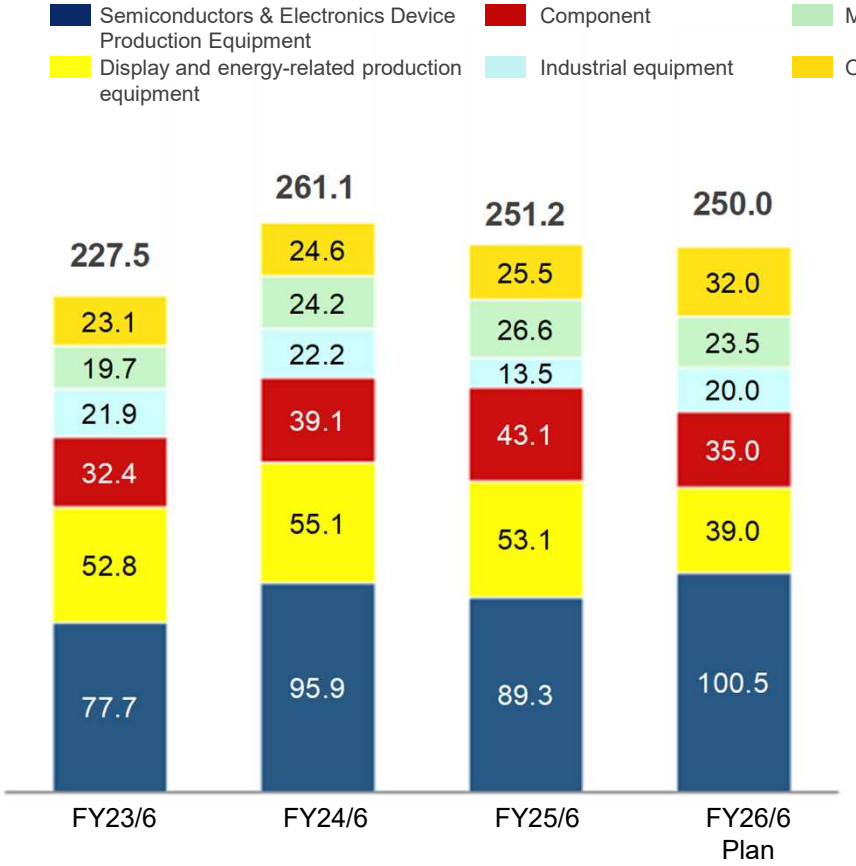
Orders Received

(Unit: ¥1 billion)



Net Sales

(Unit: ¥1 billion)



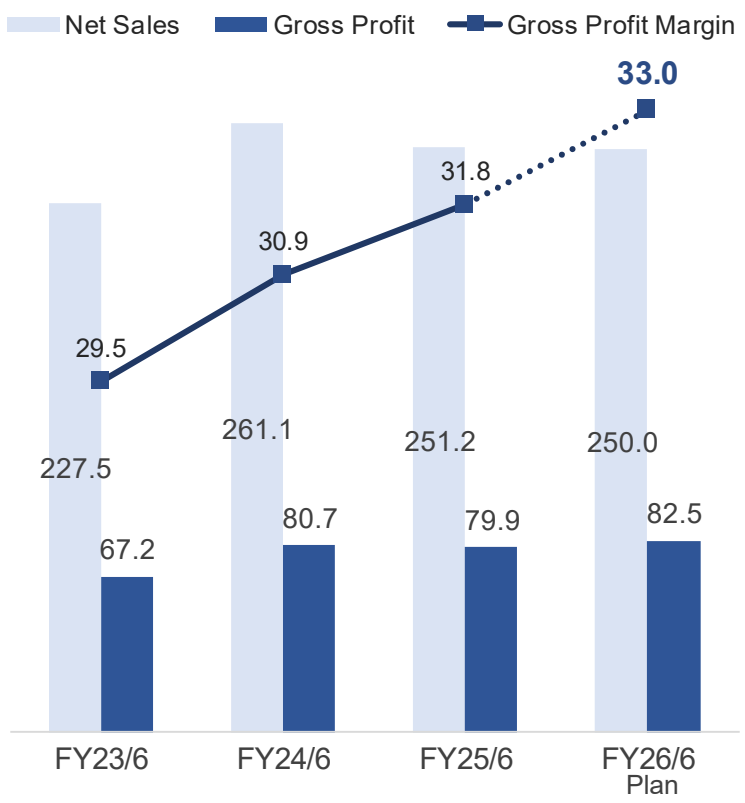
※ From FY26/6, orders received and net sales of leak test equipment have been reclassified from Components to General Industry.

Profit Margin Plan (FY26/6)

- Gross profit margin is expected to improve steadily due to an improved mix effect associated with increased sales in Semiconductors and Electronics.
- Operating profit margin is expected to improve due to the gross profit margin improvement.

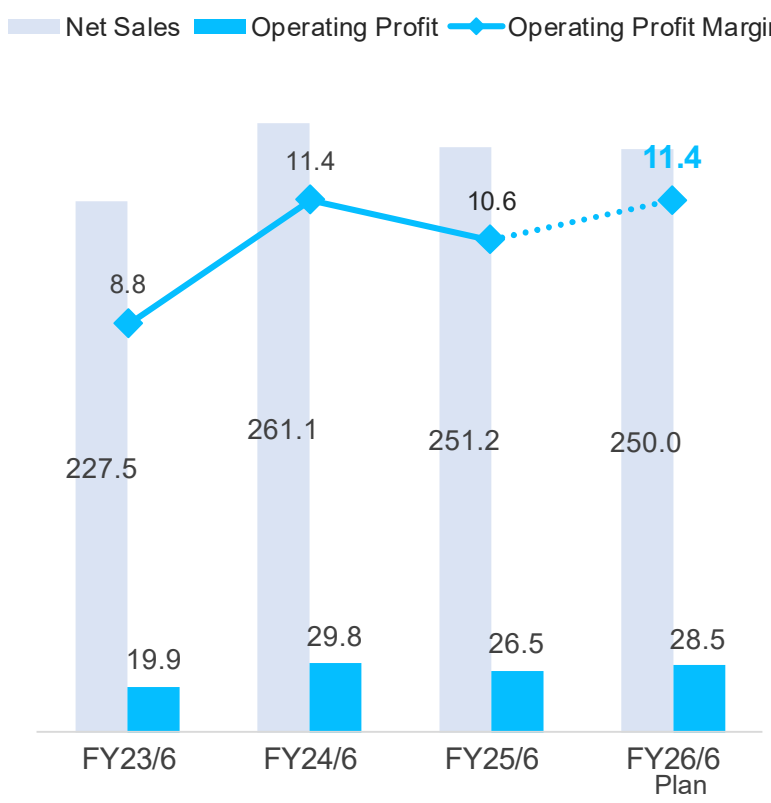
Gross profit margin

(Unit: ¥ 1 billion, %)



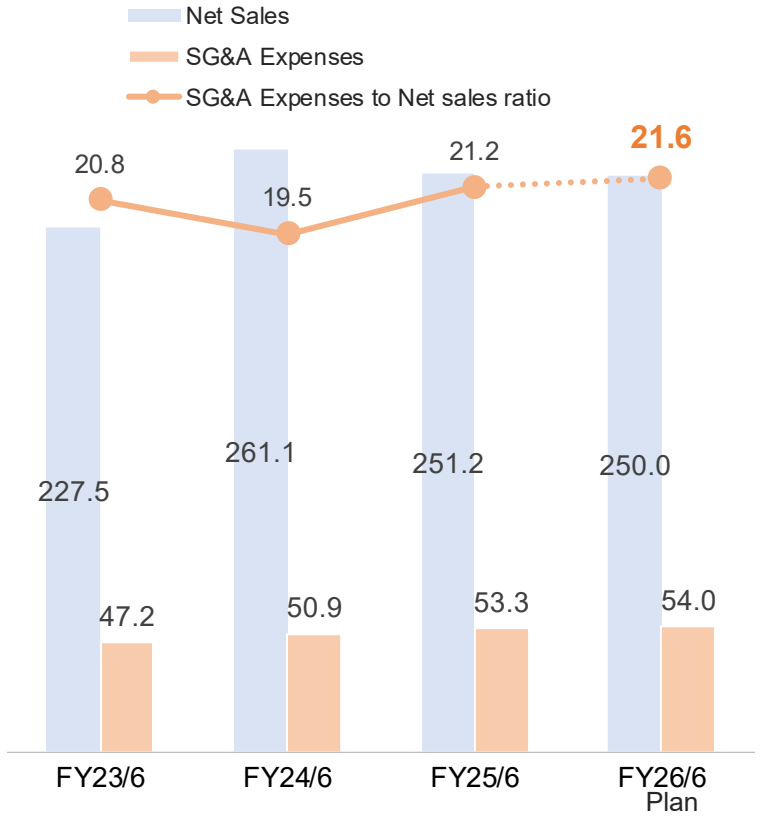
Operating profit margin

(Unit: ¥ 1 billion, %)

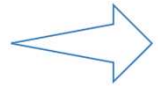


S.G.&A. Expenses(%)

(Unit: ¥ 1 billion, %)



Market Environment and Investment Trends

Item	Market Environment/ Investment Trends	CY25-CY26
Semiconductors Logic and Memory	• DRAM: Continued investments related to HBM and contributions from new customer investments • NAND: Expected expansion driven by storage demand and generative AI-related demand • Logic: Full-scale investments toward next-generation nodes and deployment of MHM processes	
Various Electronic Devices	• Continued WLP business for generative AI and contributions from PLP development investments • Investment contributions from Chinese optical device manufacturers for AR/VR	
Power Devices	• Investment recovery in 8-inch SiC mainly by major Chinese device manufacturers is expected	
Display	• Sustained contributions from additional and modification projects for equipment aimed at realizing OLED for tablets	
Battery-related	• Increased trial use of aluminum double-sided evaporation films by battery manufacturers, although mass production conversion remains slow; medium- to long-term growth expected in copper double-sided evaporation films and lithium films	
Components, General Industry, Materials, and Others	• Stable business bases with steady progress due to active capital investments in Semiconductors and Electronics and other areas • Strong performance of surface analysis systems driven by active R&D in advanced devices	

Consolidated Financial Results for FY2025/6

Earnings Forecast for FY2026/6

New Mid-Long-Term Management Plan
～Value Up Plan～

- Business Reforms
- Growth Strategy
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Basic Policy and Vision: New Mid-to-Long-Term Management Plan ~Value-Up Plan~

Selection and concentration of a business portfolio centered on semiconductors and electronics

Growth Strategy

- Accelerate focus on Semiconductors and Electronics
- Create new semiconductor and electronics-related businesses by leveraging synergies among businessses
- Expand business through M&A and other initiatives

¥110 billion increase

Consolidated net sales improvement by FY31/6

Mid-to-Long-Term Financial Targets for FY31/6

Operating profit **¥79 billion**

Operating profit margin **22%**

Business Restructuring

- Scale down and withdraw from low-profit businesses
- Restructure and streamline of group companies and production sites
- Reduce fixed costs by optimizing personnel and SG&A expenses

5.5% increase

Operating profit margin improvement by FY28/6

Production Reform

- Improve production efficiency at production sites
- Enhance profitability through modular design

12% increase

Operating profit margin improvement in the target equipment business by FY31/6

Mid- to Long-Term Financial Targets KGI

	FY25/6 Actual	FY28/6 Milestone	FY31/6 Target
Net Sales (CAGR) Semiconductors and Electronics related business**	¥251.2 billion	**¥260** billion (After Considering Downsizing and Withdrawal Due to Business Restructuring)	**¥360** billion **(CAGR 12%)** * (CAGR 17%)
Semiconductors and Electronics related business **Sales Composition Ratio**	36%	**45%**	**60% or more**
Operating Profit	¥26.5 billion	**¥39** billion	**¥79** billion
Operating Profit Margin Semiconductors and Electronics related business	10.6% 11.6%	**15%** 19%	**22%** 25%
ROE	7.5%	**10%**	**16%**

* Calculated based on estimated sales after business reform
** Based on management accounting figures of Semiconductors and Electronics Business and Related Businesses

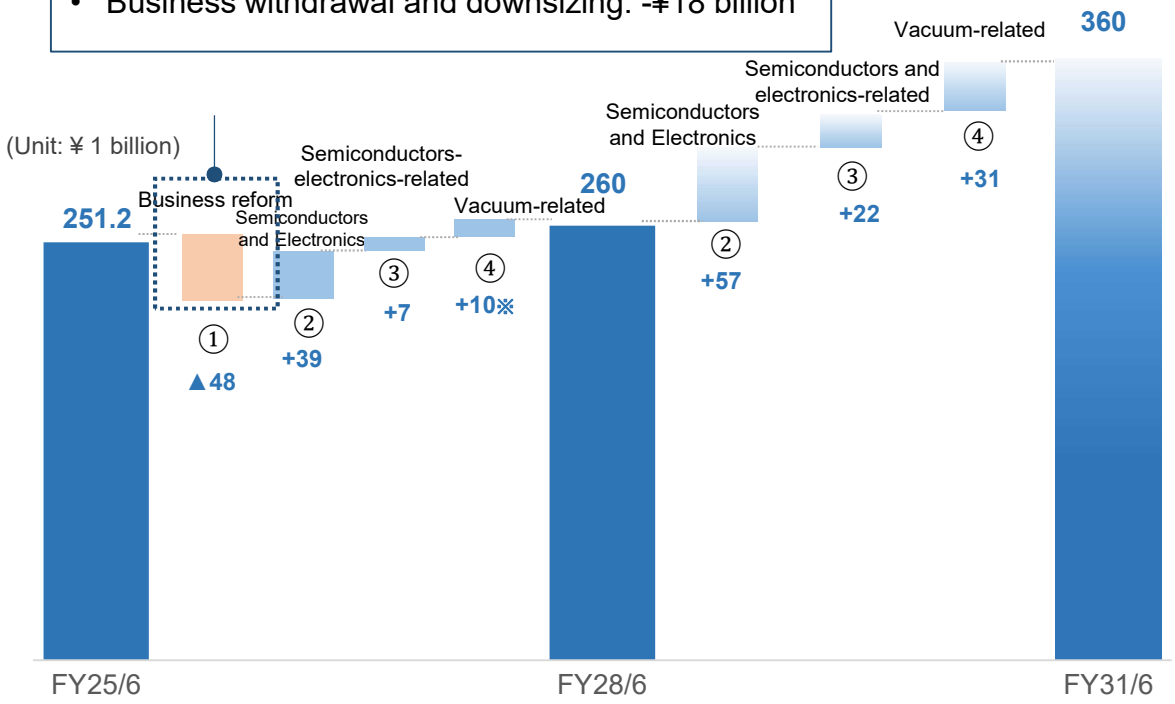
Path to Achieving Targets

» Aim to achieve steady improvement in operating profit margin by driving growth in the Semiconductors and Electronics business and related areas that exceeds the sales decline caused by business restructuring by FY28/6.

Sales Increase and Decrease Factors

① Sales decrease due to downsizing and withdrawal of low-profit businesses
② Sales increase in the Semiconductors and Electronics business
③ Sales increase in Semiconductors and Electronics-related businesses
④ Sales increase in Vacuum-related businesses

Sales decline due to business restructuring
Display-related businesses, etc.
- Business sales: -¥30 billion
- Business withdrawal and downsizing: -¥18 billion

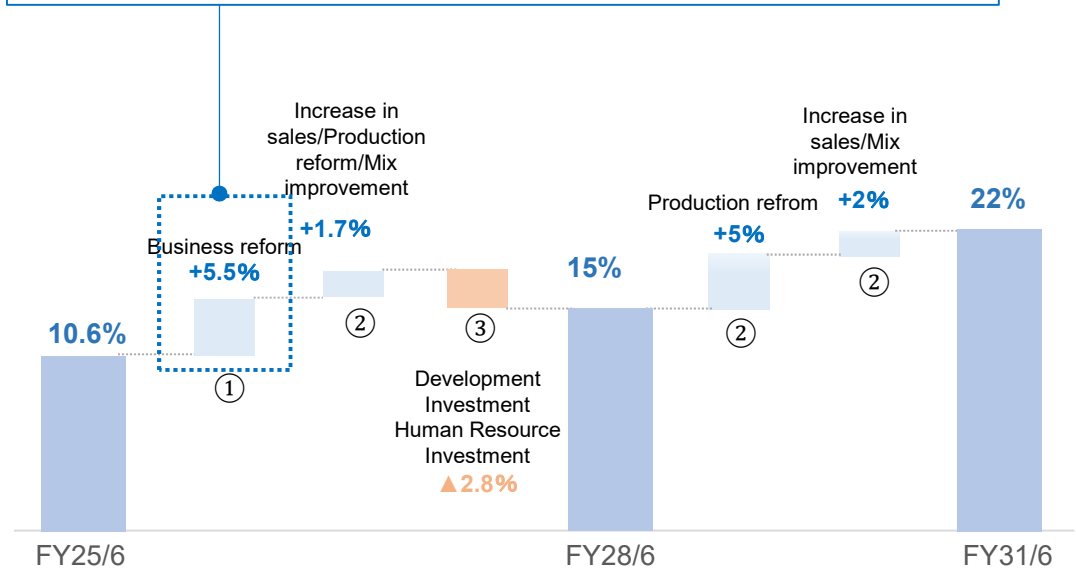


※Refer to the next page for breakdown of Semiconductors and electronics

Profit Margin Improvement through Business Restructuring

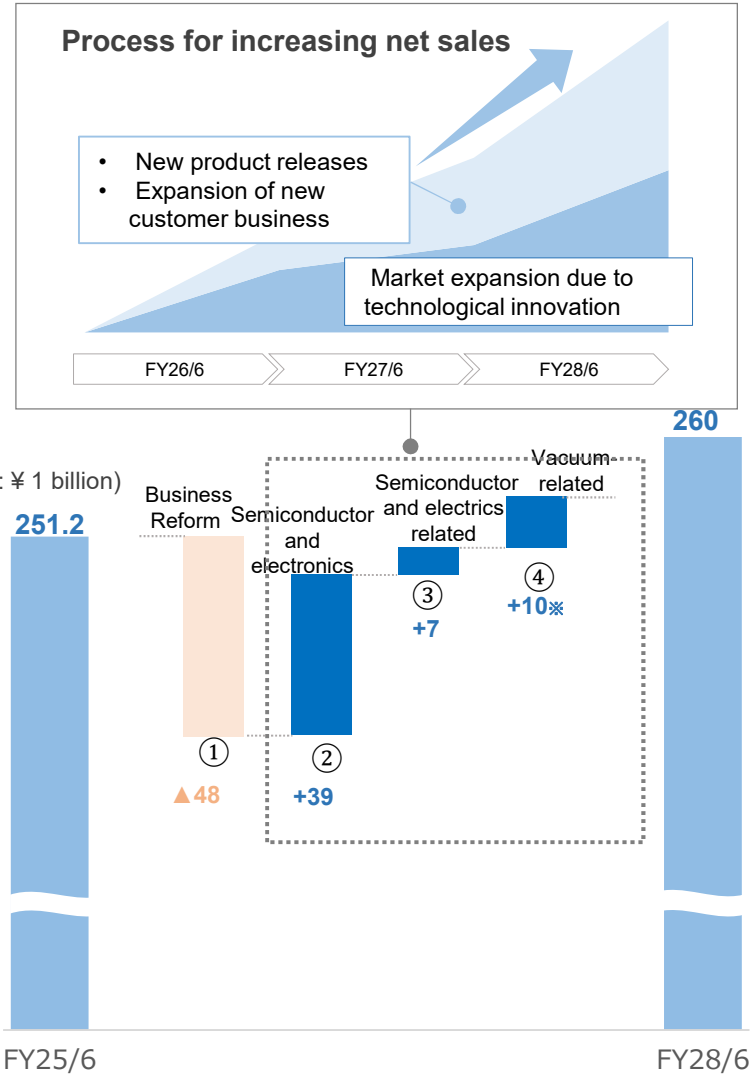
① Profit Margin Improvement through Business Restructuring
② Increase in operating profit driven by production reform, mix improvement, and revenue growth
③ Product development investment and human resource investment aimed at growth beyond FY28/6

Profit margin improvement through business restructuring
- Downsizing and withdrawal of low-profit businesses
- Restructuring and streamlining of group companies and production sites
- Fixed cost reduction through appropriate control of personnel expenses and SG&A expenses



Factors Contributing to Sales growth through FY28/6

» We aim for growth in the Semiconductors and Electronics exceeding the decline in sales resulting from business reforms through market expansion accompanying technological innovation based on existing businesses and release of new products linked to customer technology roadmaps.



■ Factors contributing to net sales growth through FY28/6

② Semiconductors and Electronics	+¥39 billion
• Memory	Increased investment in HBM + entry into new customers and new processes
• Logic	Hard mask process expansion + entry into metal film process
• Power Devices	Full-scale investment in 8-inch SiC + commencement of GaN investment
• Various electronics devices	Packaging business growth + entry into new customers and new processes

③ Semiconductors and Electronics	+¥7 billion
• Surface Analysis System	Maintaining market share in analysis equipment + entering the semiconductor inspection equipment business
• Materials (semiconductors)	Semiconductor business growth + expansion through competitive advantage products

④ Vacuum-related	+¥10 billion
• Components	Expand business by releasing new products for the Semiconductors and Electronics market
• Batteries, etc.	Progress in adoption of double-sided evaporation film to improve lithium battery safety
• Leak Testing	Expansion of multi-purpose applications such as cooling systems for data centers

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Earnings Forecast for FY2026/6

New Mid-Long-Term Management Plan
～Value Up Plan～

- **Business Reforms**
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Business Reform Policy

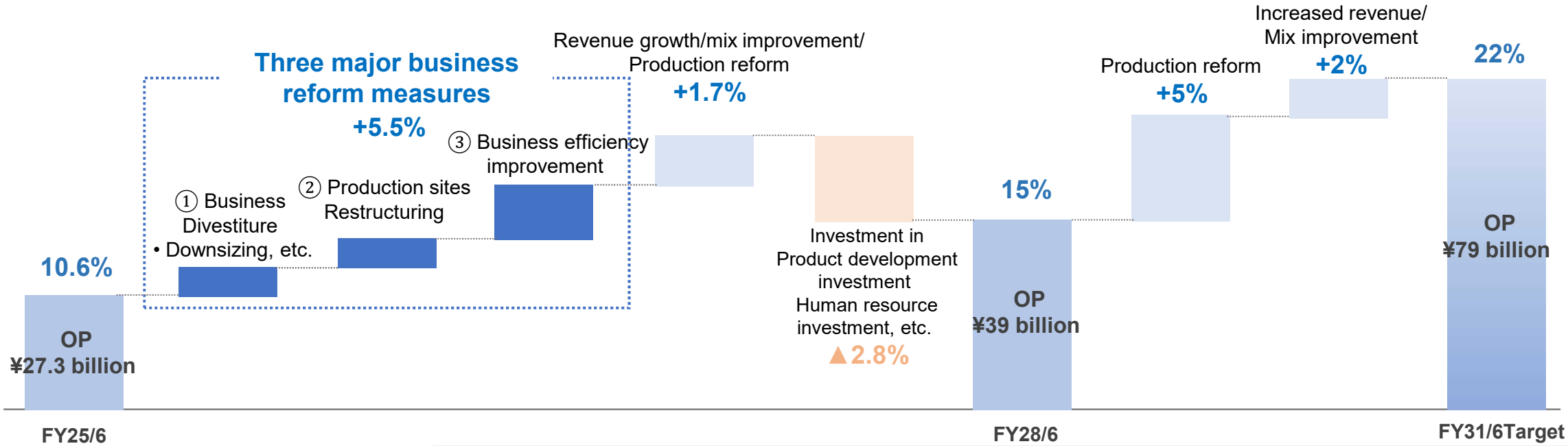
Implementing the optimization of management resources

- Scale down and withdrawal from low-profit businesses
- Restructure and streamline of group companies and production sites
- Reduce fixed costs through optimizing personnel and SG&A expenses

Completing the reforms to optimize management resources in 2 years by FY27/6
contribution to profitability anticipated from the start of FY28/6

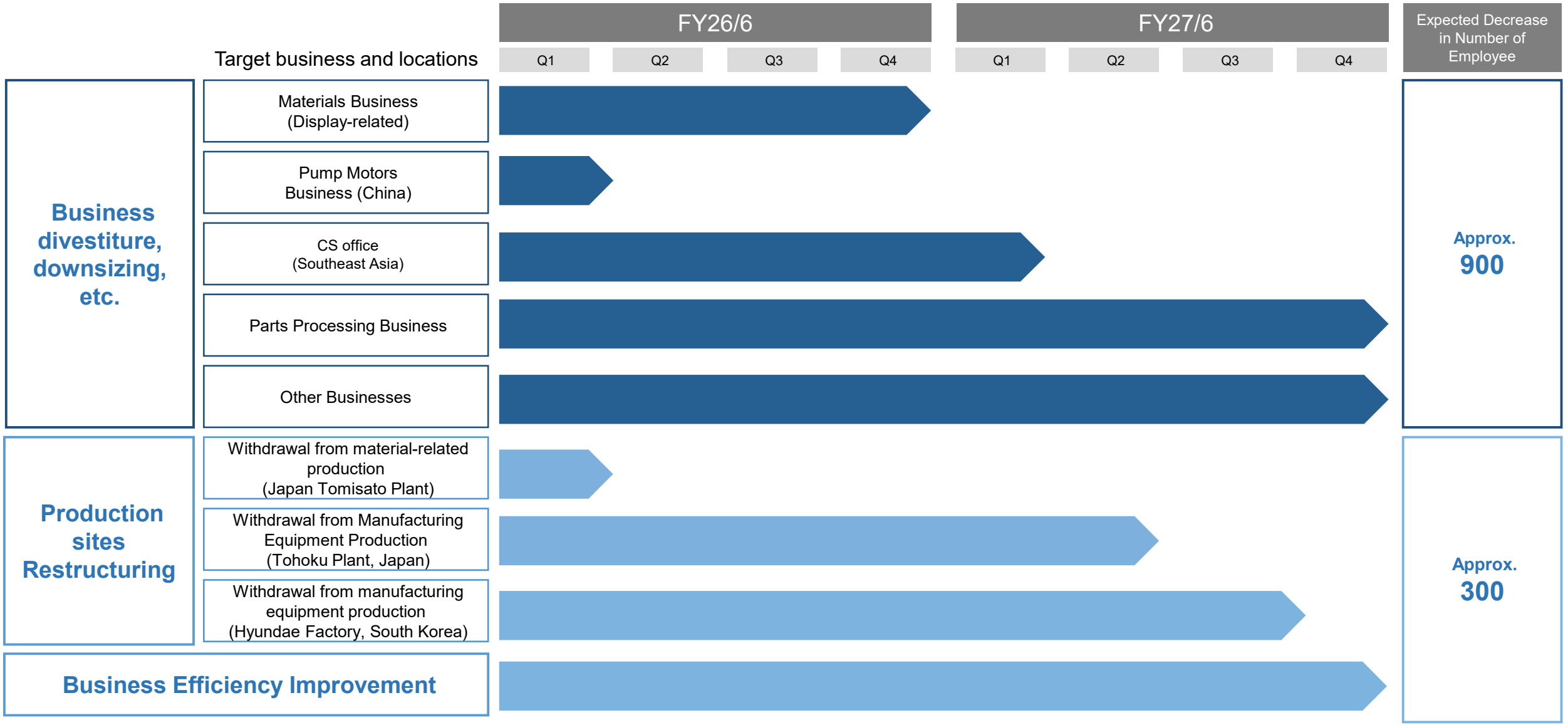
Roadmap for Achieving Targets (Factors Affecting Operating Profit Margin)

» Implement business reforms through the following three key measures to select and concentrate our business portfolio, mainly in Semiconductors and Electronics, and improve our profit margin base.



	Initiatives	Details
Business Reform	① Business divestiture, downsizing, etc.	Divestiture of 6 businesses including the transfer of equity interests to non-consolidated entities
	② Production facility restructuring	Factory downsizing (1 location), Production reduction of certain operations within the factory and conversion to other business operations (2 locations)
	③ Business Efficiency Improvement	Business efficiency improvements through integration of operations and functions, etc.
Production Reform		Reduction of variable costs through MD-based procurement and component standardization, improvement of design and manufacturing efficiency, and reduction of fixed costs through facility consolidation
Investment in Growth Areas		Investment in product development and human resources in growth areas (Semiconductors and Electronics, etc.)

Business Reform Roadmap



※ULVAC TECHNO Co., Ltd. and TIGOLD Co., Ltd. merged on July 1, 2025.

Impact of business reforms

» We expect to improve operating profit by ¥12 billion (vs. FY25/6) in FY28/6 through optimization of management resources.

Goals and Effects

Reduction in personnel

1,200
(6,200 → 5,000)

Decrease in consolidated subsidiaries

8 companies
(29 → 21)

Operating profit improvement

¥12 billion

*Improvement in consolidated performance from FY25/6 to FY28/6

Other Impacts to P/L

Although temporary expenses are recorded as extraordinary gains or losses, the impact is limited due to gains from business sales, etc.

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Earnings Forecast for FY2026/6

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Production Reform Policy

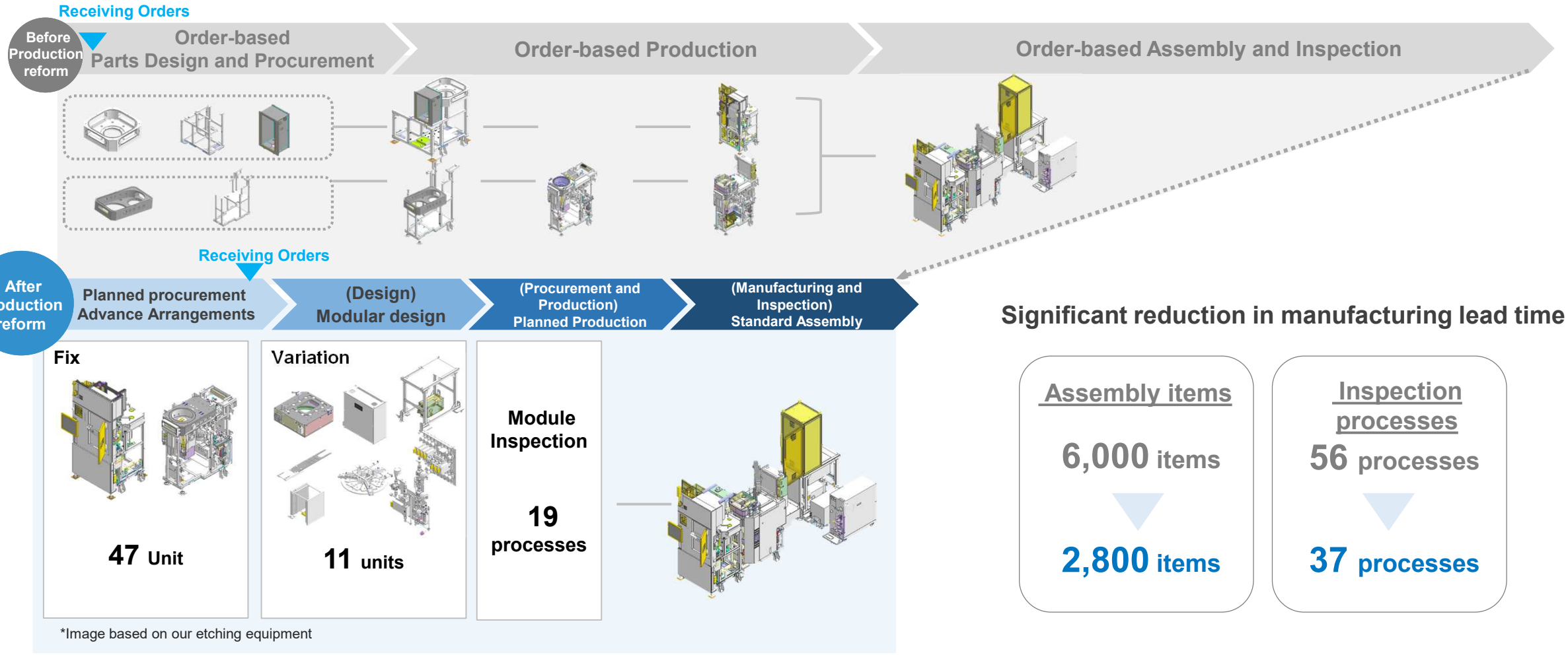
Strengthening the promotion of modular design (MD)

- Realizing volume procurement and component standardization though MD conversion ⇒ Reduction of variable costs
- Improving design and manufacturing efficiency and reducing lead time through MD conversion, and improving production efficiency by consolidating manufacturing sites ⇒ Reduction of fixed costs

Achieving profit maximization through productivity improvements

Production Reform: Overview of Modular Design

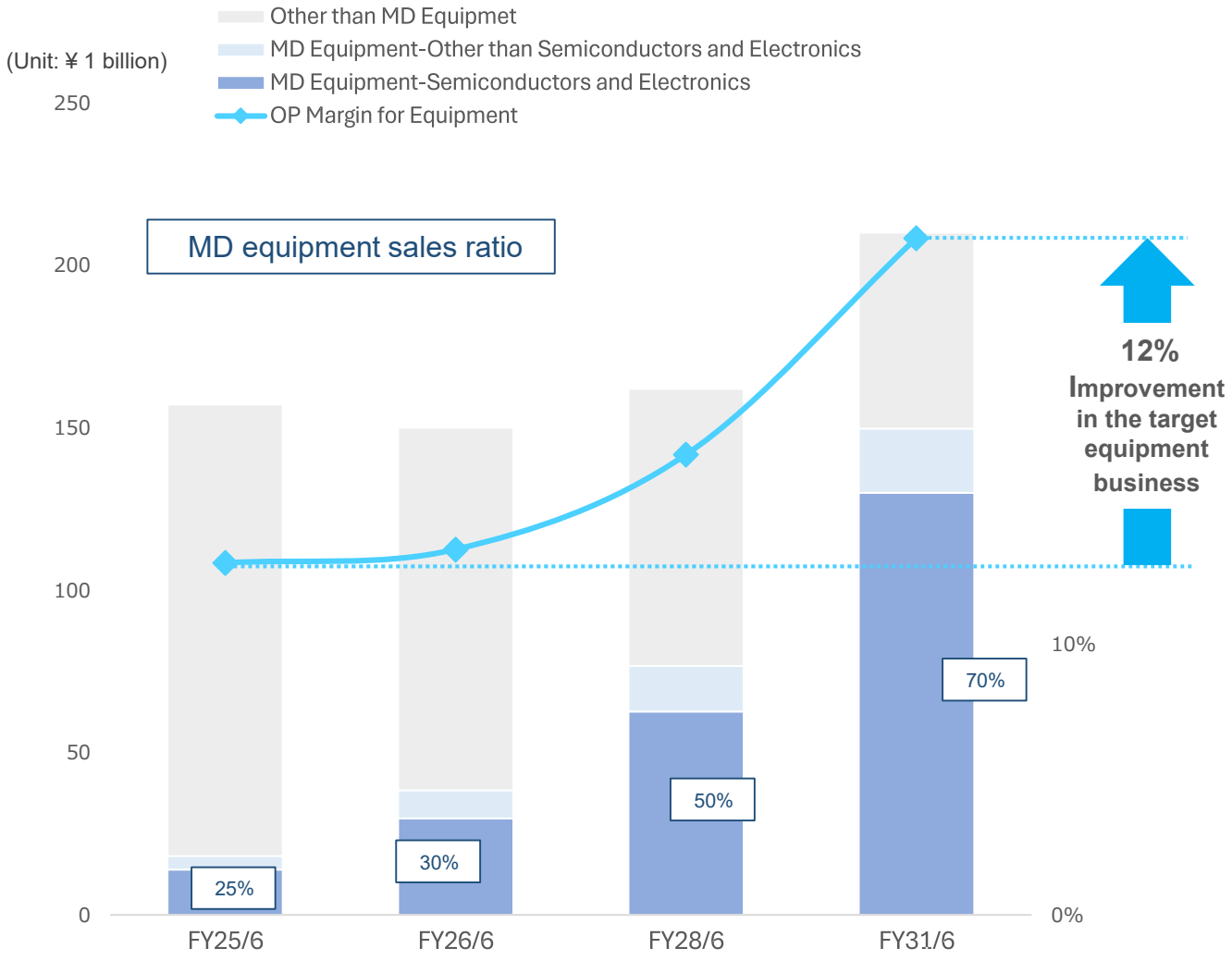
» In contrast to the conventional method of starting the manufacturing process after order receiving, the promotion of modular design enables advance preparation and planned production. By establishing an efficient production system, it is possible to reduce manufacturing lead time (L/T) significantly .



Significant reduction in manufacturing lead time

Assembly items	Inspection processes
6,000 items	56 processes
▼	▼
2,800 items	37 processes

» By increasing the proportion of modular design equipment centered on semiconductors and electronics, we will swiftly respond to customer needs and achieve profitability improvement through the consolidation of manufacturing sites.



Production reform effects by FY31/6 (target equipment business)

Procurement lead time reduction, variable cost (rate) reduction

- Parts commonization and planned bulk ordering to reduce parts prices
- Parts procurement aligned with assembly schedules

Reduce design man-hours and shorten lead time

- Combinations that do not require changes to drawings (compatible design) Achieve customer specifications

Reduced manufacturing lead time, increased shipment volume, and reduced labor hours

- Production optimization through standard assembly and planned production

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Growth strategy guidelines

Further growth centered on semiconductor electronics

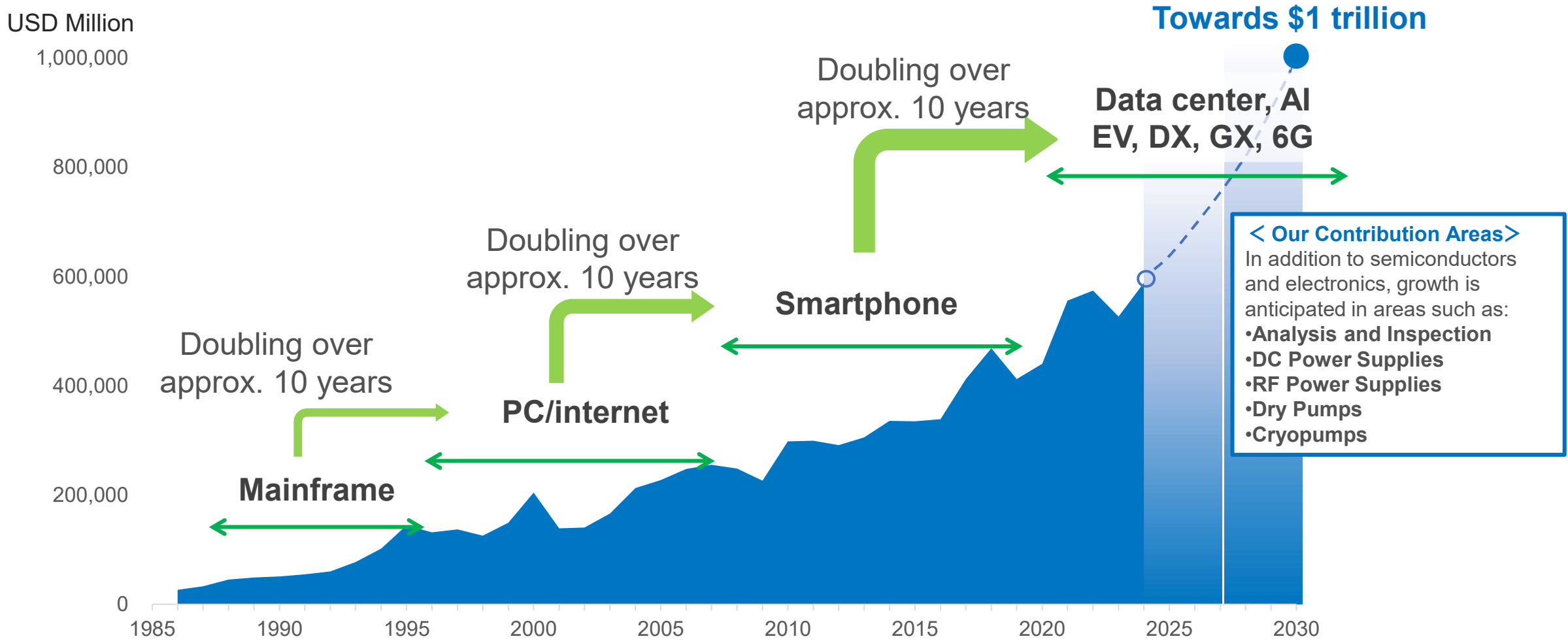
- Create of new semiconductor and electronics-related businesses by leveraging synergies among businesses
- Accelerate the growth in the semiconductor electronics business
- Expand AI-related business
- Expand business through M&A

Strengthening the business foundation to pursue high growth and high profitability through the transformation of our business portfolio centered on semiconductor and electronics

Growth Strategy

» The semiconductors and electronics market is expected to grow to $1 trillion by 2030.

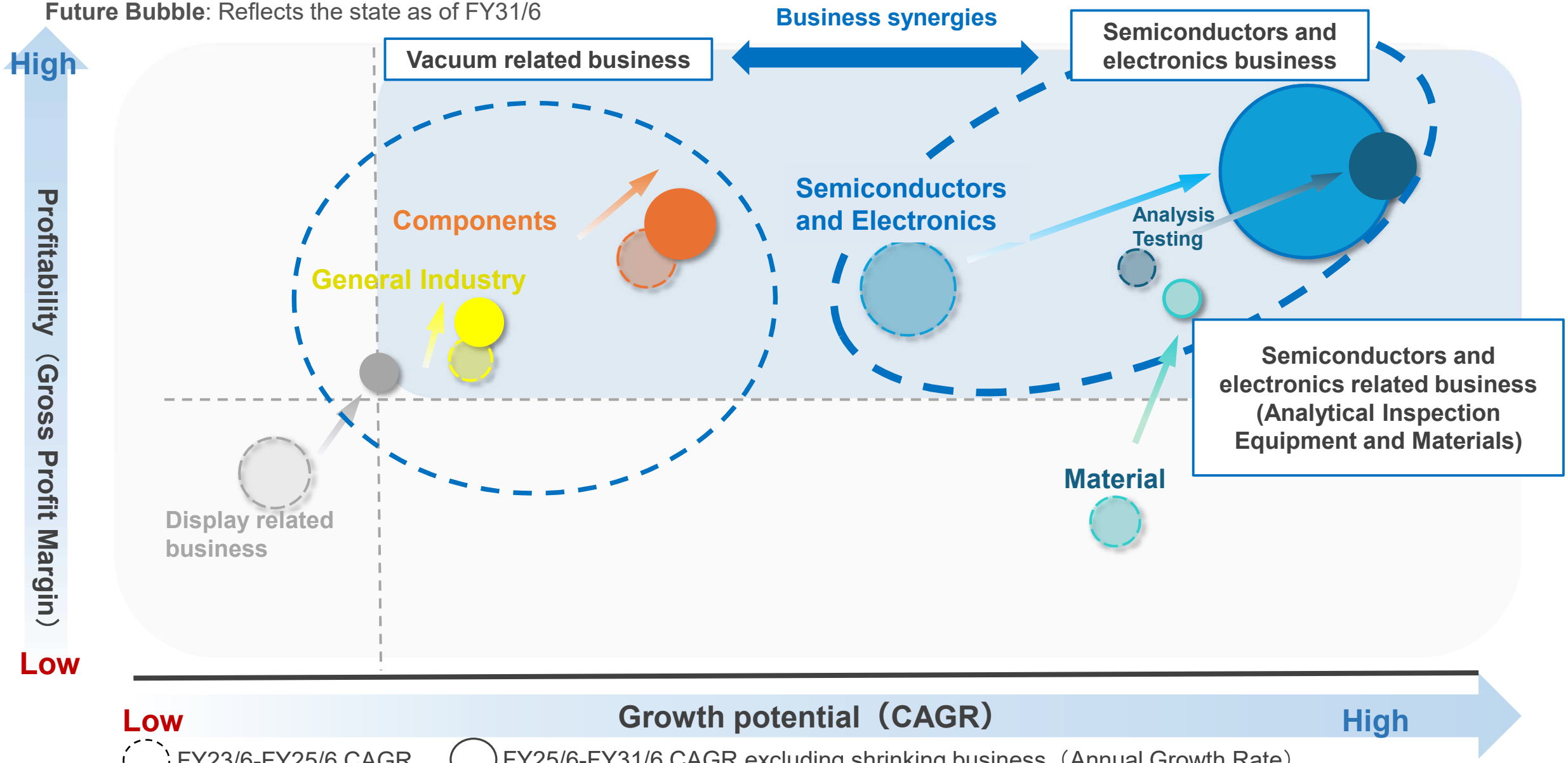
Growth of the semiconductors and electronics Market



Source: WSTS、SEMI

Growth Strategy : Business Portfolio Strategy Image

Bubble Size: Represents net sales / **Arrow Direction**: Indicates future position /
Future Bubble: Reflects the state as of FY31/6



Transition of Semiconductor & Electronics Sales Composition Ratio

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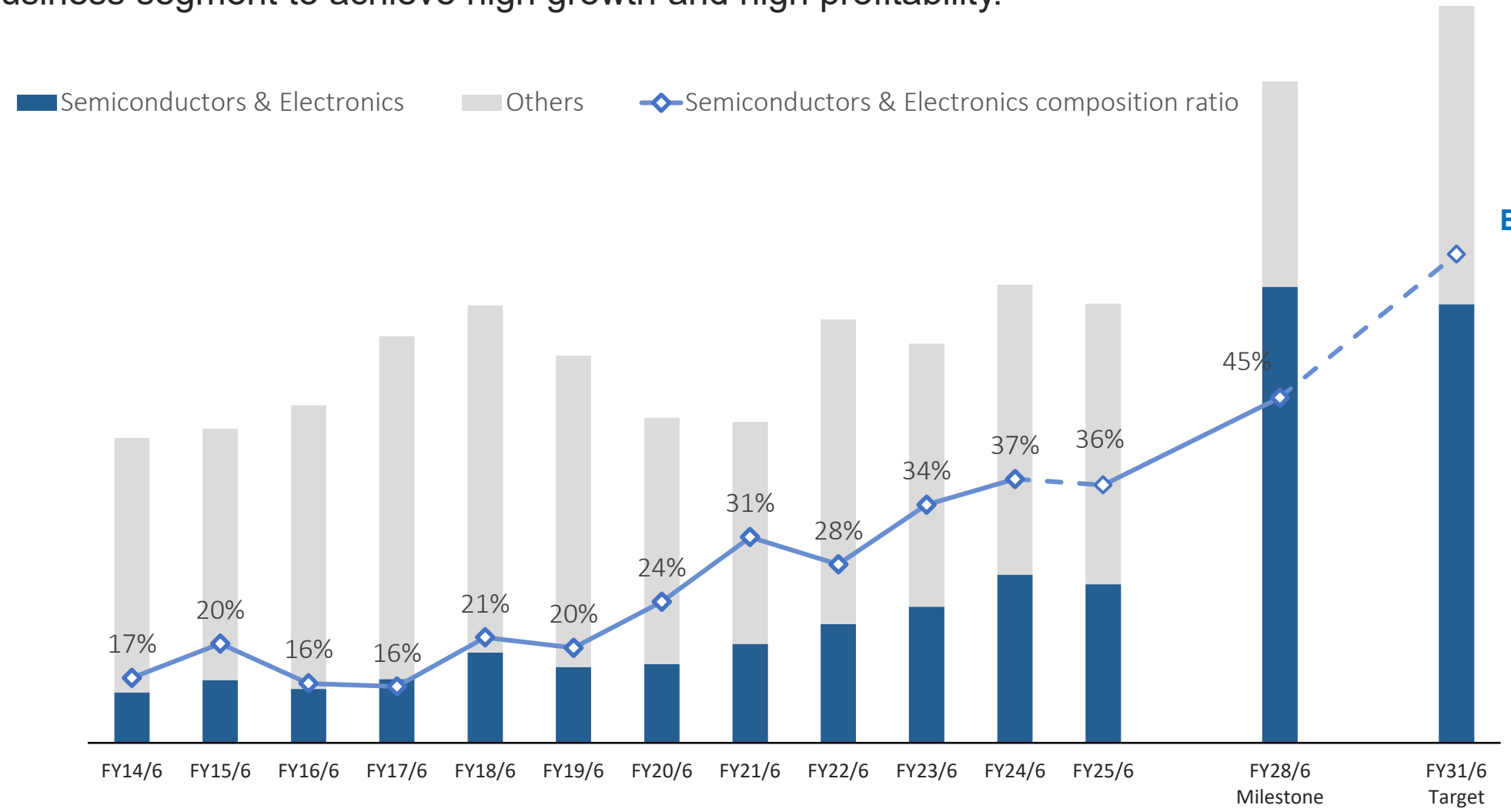
» Based on the lean structure achieved through the Value-Up Plan, we will accelerate our focus on semiconductors and electronics and create new semiconductor & electronics-related businesses by leveraging synergies across business segment to achieve high growth and high profitability.

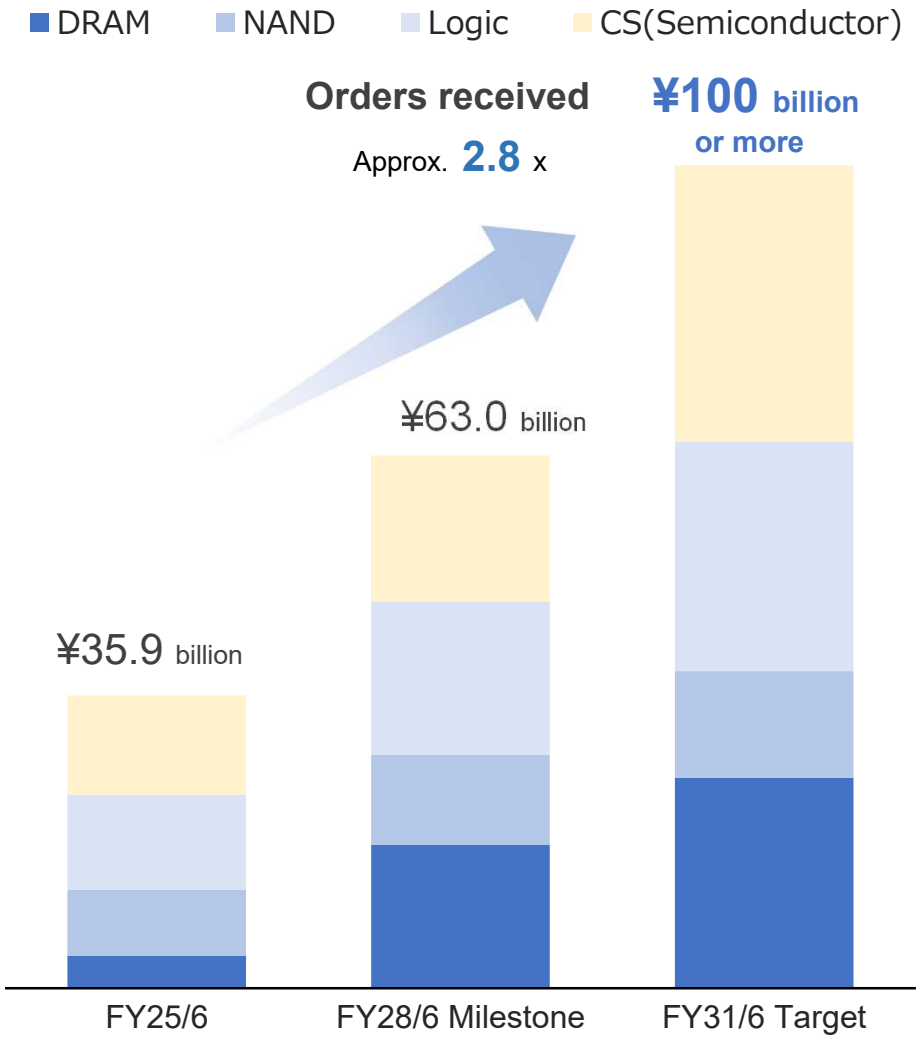


Semiconductors & Electronics- Related Business Composition Ratio

60% or more

Growth Strategy : Semiconductor Growth Scenario

» Based on proven hard mask technology and metal film deposition technology, we will increase the number of POR*s for important customers and expand our market share by acquiring new processes, aiming for orders of ¥100 billion or more in FY31/6.



Growth Strategy

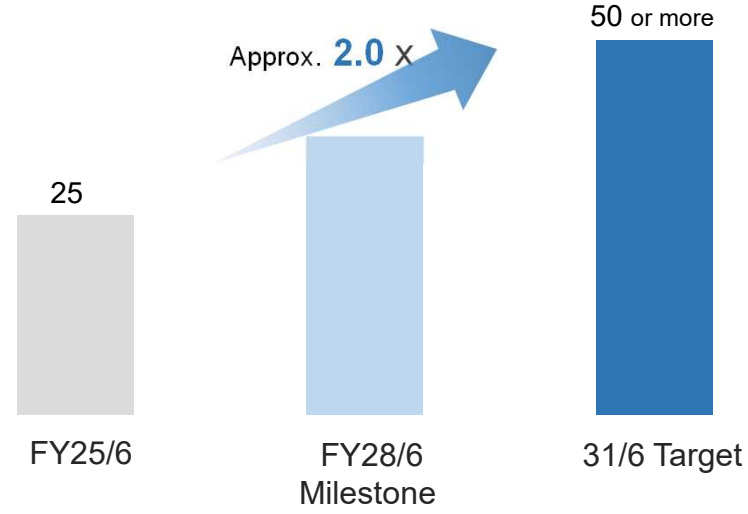
① Apply HM (Hard Mask) technology to high-density functional films.

② Establish a top position in HM processes and expand into Cu wiring applications.

③ Expand PVD market share by securing advanced logic Cu wiring and post-Cu wiring processes.

④ Expand and deepen the CS (Customer Support) business.

Number of important customers POR



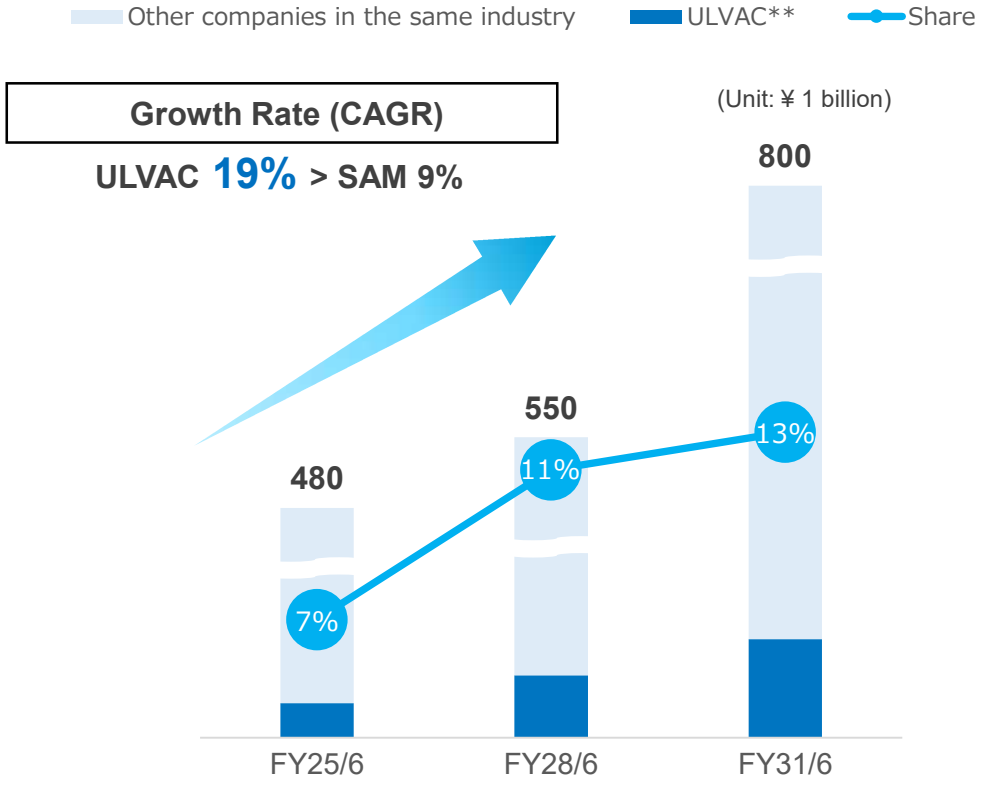
* Process of Record: Certified process used in mass production

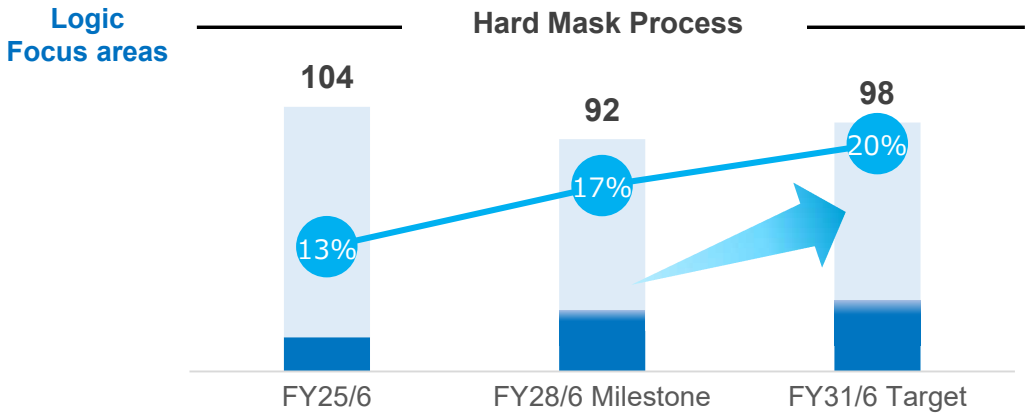
Semiconductor Market Size & Our Position

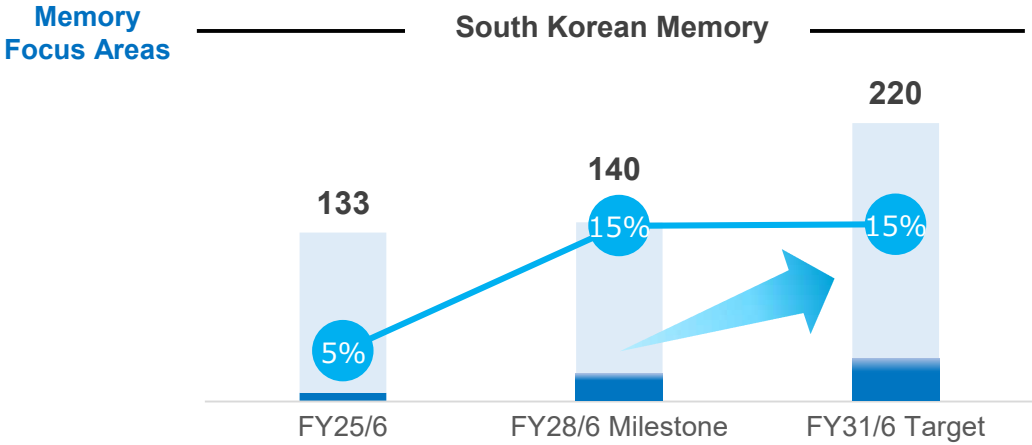
» To achieve growth exceeding the growth rate of the semiconductor sputtering market, we are pioneering new processes in the logic field using hard mask technology and accelerating joint development with South Korea's top manufacturer in the memory field to expand our market share.

Semiconductor Sputtering Equipment Market* (SAM) & Our Market Share

Semiconductor Sputtering Equipment Market
(Top 6 Companies + Mature Logic)







* Based on estimates by our company using data from Gartner, etc.
** Order volume (including CS)

Semiconductor & Logic Growth Roadmap

Technology Trends	Our Strengths
Progress in miniaturization	Stress control
Introduction of new materials	Low-particle film deposition
	Low-temperature film deposition technology

■ Growth Roadmap

Expansion of new materials and low-resistance film deposition technologies

Low-resistance new materials

☆ Proven track record

Acquisition of advanced logic metal wiring processes

Cu interconnect | Al/W Process

Hard mask technology development leveraging stress control and low-particle deposition

★Hard masks for BEOL wiring formation | ★Hard masks for GAA formation | Hard mask for back-side wiring formation

Customer Technology Roadmap	2024	2025	2026	2027	2028	2029	2030	2031
Logic	2nm		A14		A10		A7	

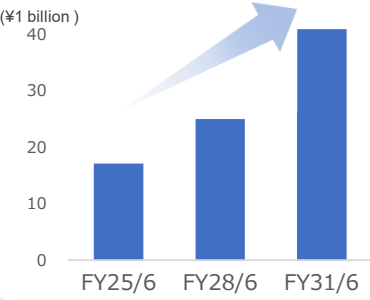
Mid- to Long-Term Goals

Hard Mask PVD+ Securing market share through the capture of the metal wiring process

- Centering on metal hard mask technology, which is the de facto standard at 5 nm and 3 nm, we aim to establish a market share in hard mask applications and related process technologies.
- Aiming to enter and expand into the metal wiring process, where PVD is most widely used

Orders Received

Approx. **2.4** x



Semiconductor and Memory Growth Roadmap

Technology Trends	Our strengths
Progress in miniaturization	Low-particle film deposition
Acceleration of 3D structures	Stress control
Introduction of new materials	High-density film formation

■ Growth roadmap

CVD and ALD integration

Under development with leading memory manufacturers

Development of new materials and low-resistance film deposition technologies, and expansion of mid-process wiring

Cu bonding　　New Materials

☆ Proven track record

Expansion of cutting-edge memory processes such as　metal film processes and HM processes. and customer expansion

★ Cu, Al, W, and TiN wiring processes　★ HBM wiring processes　Back-side Film Deposition (Bonding, Stress Control)

Customer Technology Roadmap	2024	2025	2026	2027	2028	2029	2030	2031
DRAM	13nm	<12nm		<11nm		<10nm		
NAND	288L		3XX		4XX		4YY	

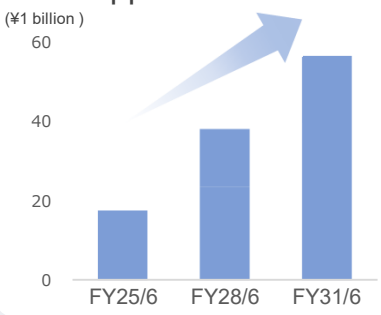
Mid- to Long-Term Goals

Maximizing market share in memory processes

- Accelerated joint development with a leading Korean manufacturer to expand the number of processes (utilizing the Technology Center)
- Expansion of processes through the provision of solutions compatible with new materials and structures

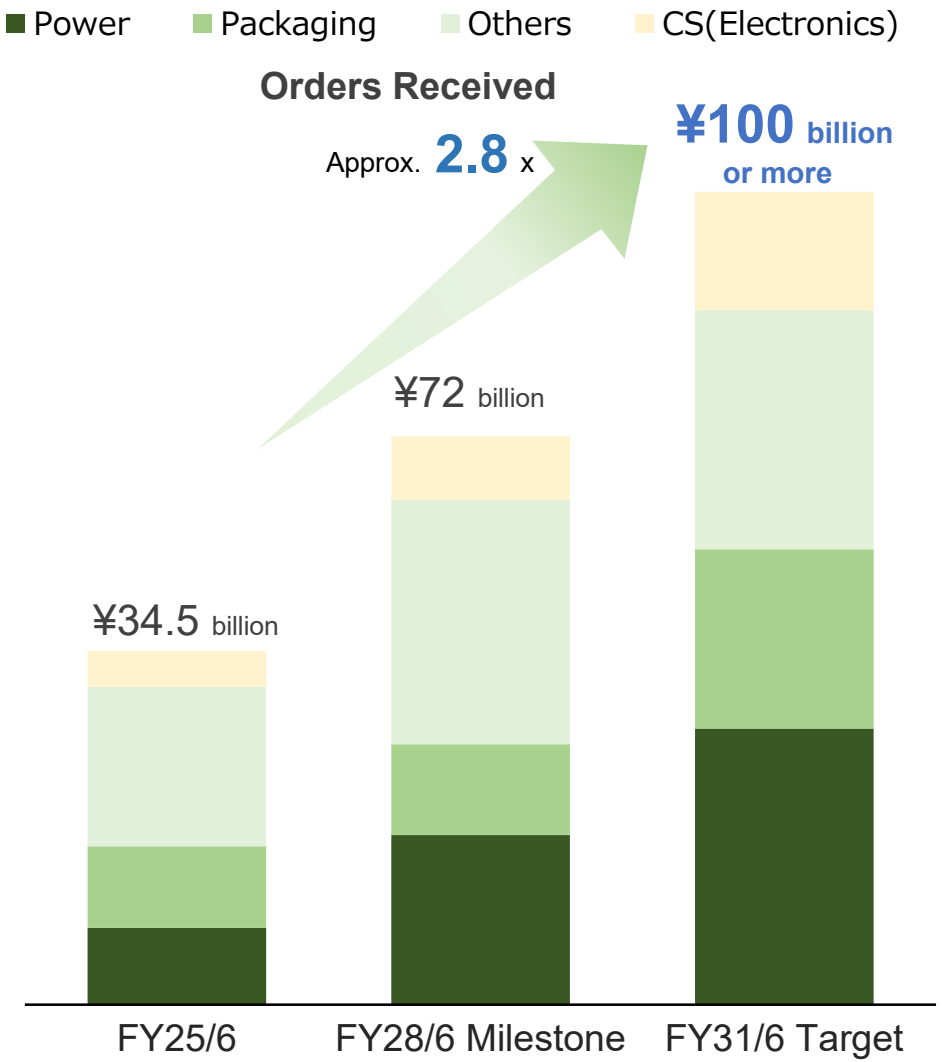
Orders Received

Approx. **3.6** x



Growth Strategy: Growth Scenario for Electronic Devices

» We aim to expand to a business scale of over ¥100 billion and further growth mainly through the revitalization of the packaging business and the recovery of power device investments.



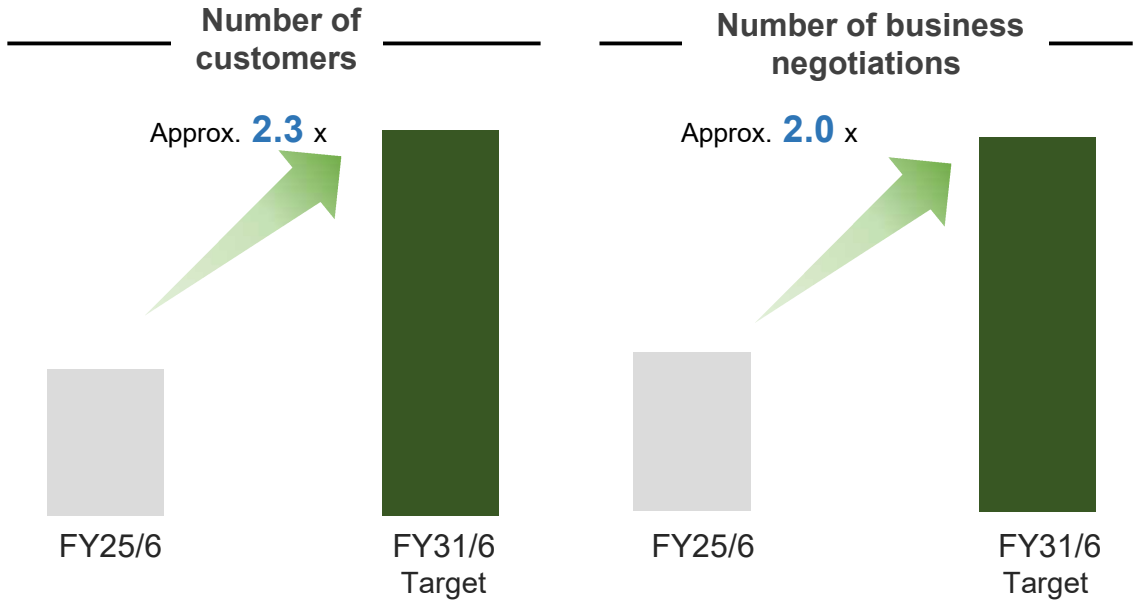
Growth Strategy

① Expand applications to support GaN mass production in addition to SiC sputtering and ion implantation.

② Capture new processes and benefit from increased investment in advanced packaging.

③ Develop optoelectronic fusion businesses through mass production of TFLN (Thin Film Lithium Niobate) etching, contributing to the miniaturization of communication devices.

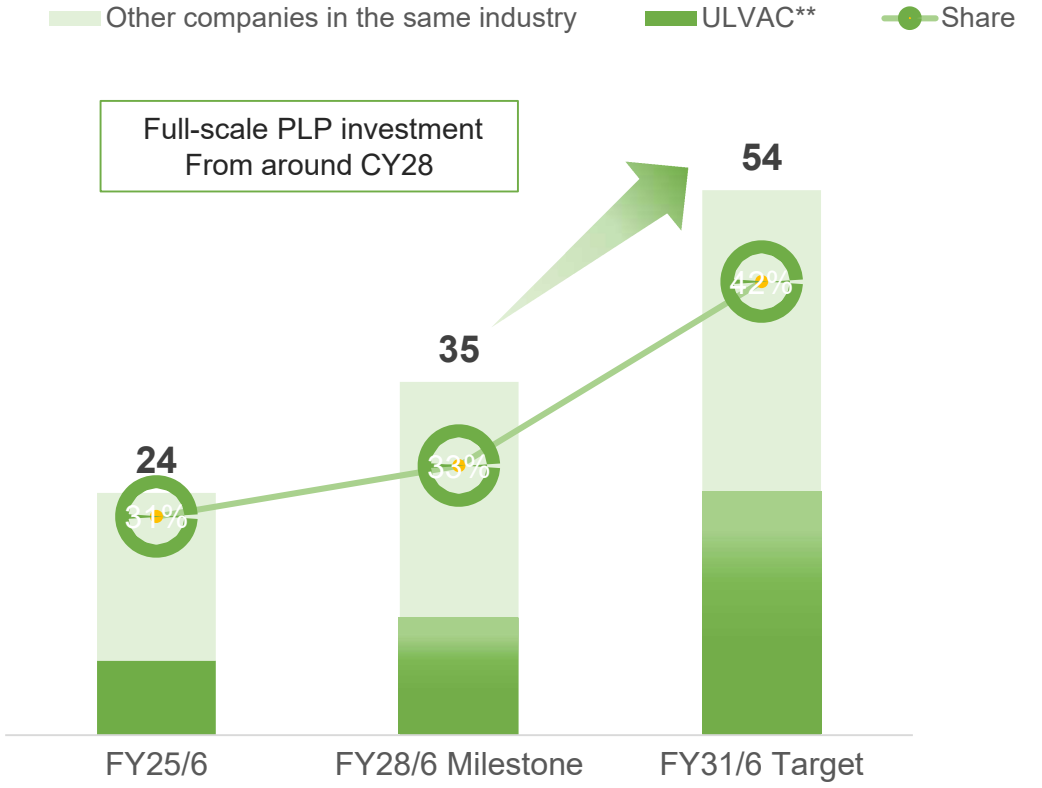
④ Expand and deepen the CS business.



Electronic Device Market Size & Our Position

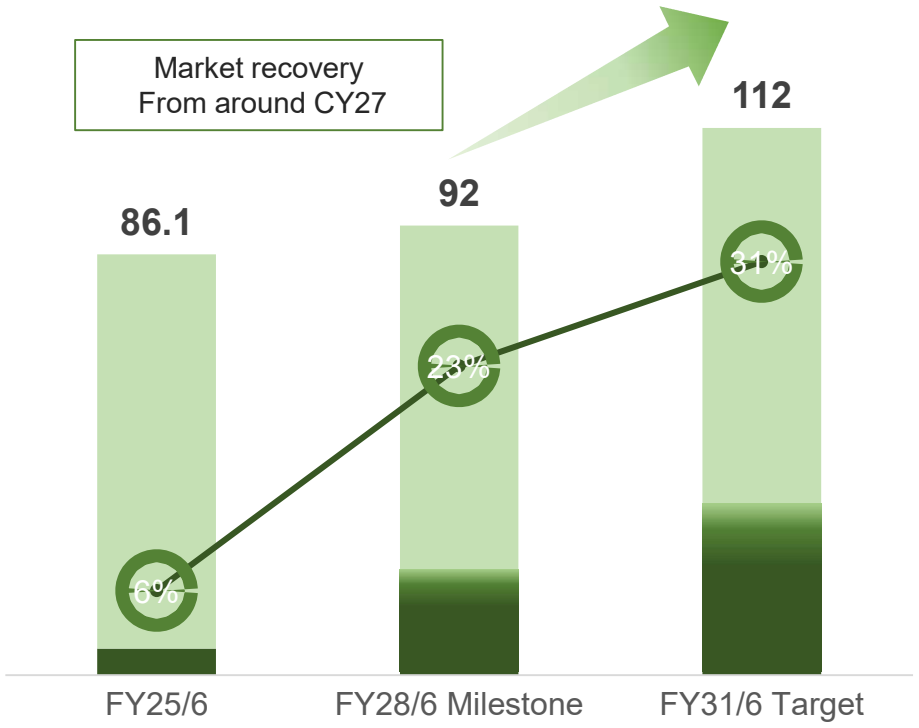
- With the expansion of the AI server market, the package market will continue to grow. We expand our share mainly in the advanced package and ashing fields.
- The power device market is expanding due to the advancement of electrification and energy efficiency. We are expanding our share by responding to innovative technologies.

Packaging & Ashing Market SAM* & Our Market Share



Power Device Market (SiC, GaN) SAM* & Our Market Share

(Sputter and Implanter Equipment Market)



* Based on our estimates
** Order volume (equipment only, excluding CS)

Electronic Devices and Packaging Growth Roadmap

ULVAC

Technical trends	Our strengths
Progress in miniaturization	Low-damage plasma technology
Introduction of new structures	Glass Substrate Film Deposition/Processing Technology
Expanded substrate area	

■ Growth Roadmap

☆ Proven track record

○ Release Schedule

Expansion into next-generation packaging

- Next-generation Panal desmear
- Direct Via Etching

Expanding opportunities through the expansion of packaging substrates

- Desmear for package substrates
- Descum for packaging substrates
- Electrode formation sputtering

Dominance in advanced packaging equipment leveraging plasma technology and expansion of new processes

- ★ Decum for interposers
- Plasma Surface Activation (Hybrid Bonding)
- Plasma dicing

Our Development Roadmap	FY26/6	FY27/6	FY28/6	~FY31/6
WLP PVD/Etch	★	● ●		
PKG Subst.	●	●	●	
Next-generation panel PVD/etching		●	●	

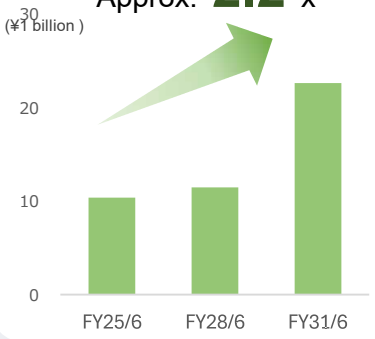
Mid- to Long-Term Goals

Become the only unique player in the packaging process

- Maintaining the No. 1 market share for ashing equipment for the descum process
- Expanding PLP business with expertise cultivated through FPD technology
- Continuous release of various devices compatible with new structures for business expansion

Orders received

Approx. **2.2** x



Electronic Devices and Power Devices Growth Roadmap

Technical trends	Our strengths
Introduction of new materials	High reliability based on extensive experience
Introduction of new structures	Compound film deposition and processing

■ Growth Roadmap

☆ Proven track record
○ Scheduled Release

Providing solutions tailored to new materials

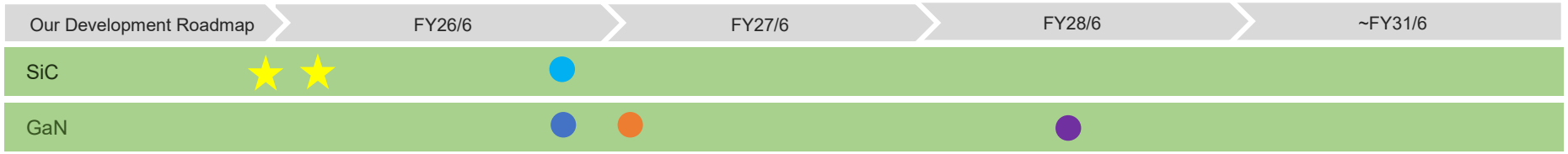
Gallium Oxide (Ga_2O_3) | Diamond

Development of Gallium Nitride (GaN) Compatible Technologies

GaN sputtering | GaN etching | 12-inch compatible GaN sputtering

Maintain market share for silicon carbide (SiC) compatible devices and aim for further expansion

★ SiC Ion Implantation | ★ Back-side electrode sputtering | Front-side wiring formation sputtering

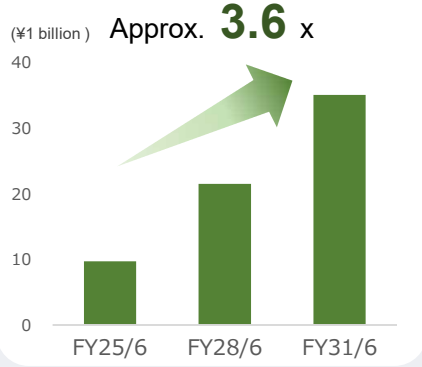


Mid- to Long-Term Goals

Providing optimal solutions for innovative power device technologies equipment solutions

- Maintaining top market share in China for SiC ion implantation equipment (share: over 70%)
- Maintaining the top market share in Japan for back-side electrode sputtering equipment (market share: over 70%)
- Flexible adaptation to evolving material changes from SiC to GaN to new materials

Orders received

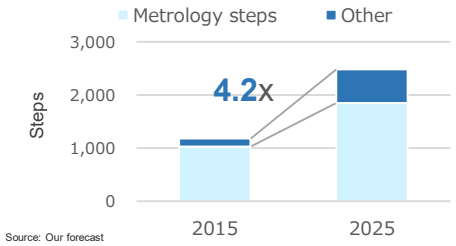


Growth Strategy: Analytical Inspection Equipment - The Challenge of Moving from Lab to Fab

» Leveraging experience and achievements in the existing Lab-type model (market share No. 1), we aim to establish a global position in the inspection equipment market by fully introducing "XPS" into the Fab-type model, where the importance of analysis increases due to the advancement of manufacturing processes, through synergies between semiconductor electronics and other businesses.

Market Environment

The semiconductor manufacturing process has doubled in the past 10 years, with the inspection process increasing fourfold.



Technology and Market Trends

- Increase in process steps due to advances in miniaturization
- Growing demand for yield improvement
- Increased importance of quality control

Our Strengths

- Our track record as surface analysis specialist manufacturer
- R&D to service integrated system
- Providing value from both Software (Science) /Hardware (Physical and Optical Design,Manufacturing)

by FY25/6

Top share in XPS analysis equipment for research and development

- Expansion of XPS analysis equipment for research and development
- Prototype development of XPS inspection equipment for semiconductor mass production lines

XPS analysis equipment for research and development

by FY27/6

Market launch of XPS inspection equipment for semiconductor mass production lines

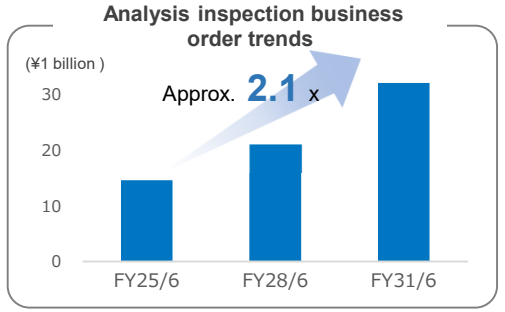
- Improvement of XPS analysis equipment for research and development
- **Product release of XPS inspection equipment for semiconductor mass production lines**

XPS inspection equipment for semiconductor production lines Image

by FY31/6

Aiming for further expansion through scaling global operation

- Expansion of the lineup of analytical instruments for research and development
- Expansion of production capacity for XPS inspection equipment for semiconductor mass production lines
- Commercialization of a business generating **¥30 billion** in orders for analytical instruments and inspection devices



Growth Strategy: Expansion of Component Business

» We aim for further growth through refining our strength in offering a comprehensive product lineup that is suitable for a wide range of markets and applications, from general industries to semiconductors, electronic devices, and the medical field, and aim for growth.

Vacuum Pumps

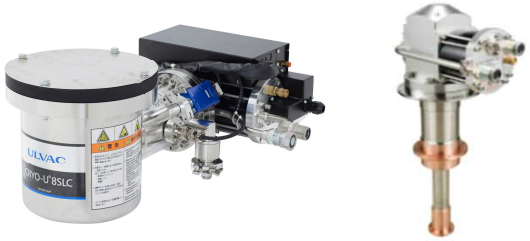
Expanding sales into diverse markets and applications

Dry Pumps

In addition to our domestic top share in the scientific and analytical market with compact pumps, we are expanding our pump lineup for the semiconductor and electronics market to increase our share.

Cryopumps/4K and Dilution Refrigerators

Exploring new markets with cooling technology



Low-temperature equipment (cryogenic)

Expanding the use of compact, energy-efficient cryopumps in the semiconductor electronics field

Applying ultra-low temperature technology to challenge the medical field and quantum computer market

Measuring instruments and film deposition power supplies

Accelerating global expansion through alliances

Helium Leak Detector

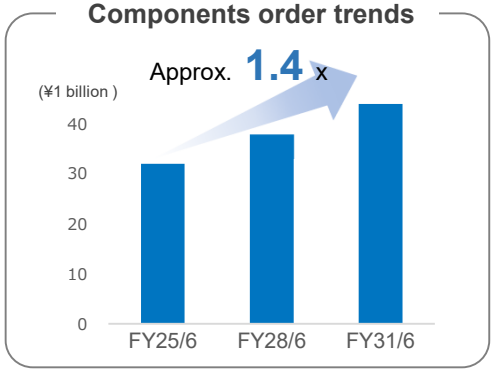
In addition to expanding EV-related businesses, we aim to expand orders for the global semiconductor market by strengthening alliances.

Expanding market share through the deployment of digital control power supplies

10kW Digital DC Power Supply

Expanding digital control technology into DC, RF, and EB power supplies to expand sales in the semiconductor and electronics markets

Introducing new products such as energy-efficient RF power supplies and space-saving EB power supplies



Growth Strategy: Innovation in Vacuum-Related Businesses

» Maximizing the potential of vacuum technology to create new value and drive growth

Heat Treatment Furnaces

General industrial equipment

Enhancing the competitiveness of legacy equipment

Sintering and heat treatment furnaces

Maintaining a high market share with high-performance heat treatment furnaces. we are advancing equipment efficiency and optimization to provide competitive solutions by leveraging expertise in large-scale mass production equipment developed in the FPD field,

Leak Testing Equipment

General industrial equipment

Expanding business through application development

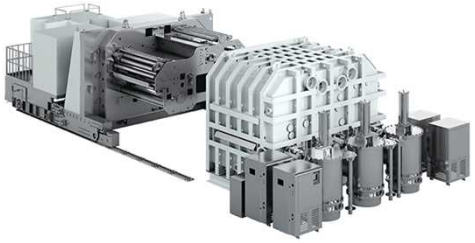
EV battery leak testing equipment

Maintaining a high market share in high-performance leak testing equipment. In addition to air conditioning and EV applications, we excel in customization and adaptability for a wide range of applications, including cooling systems for data centers

Roll to Roll

Display and Energy-Related Manufacturing Equipment

Improving production efficiency through diversification to capture market share

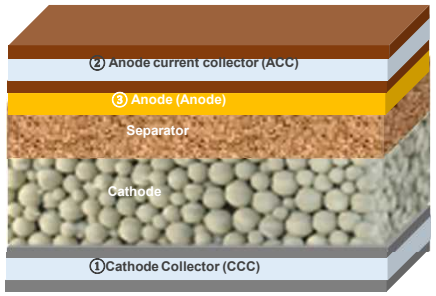


Double-sided roll to roll deposition equipment
(Model compatible with 1.6m film width)

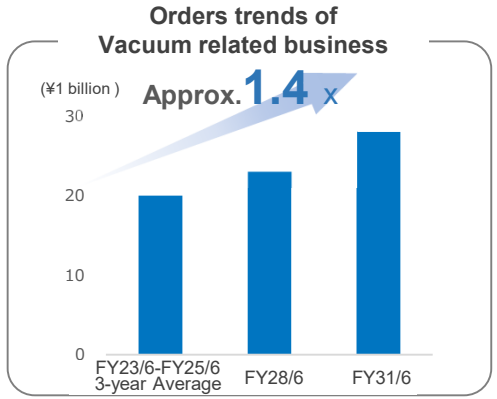
As the demand for improved safety in lithium batteries grows, attention is increasingly focused on Al double-sided deposition films (Figure 1, ①). By enhancing productivity through increased film width (from 1.6m to 2.5m), we aim to reduce production costs per unit area and accurately address evolving technical requirements, thereby maintaining our leading position.

Development of Cu double-sided deposition film for ACC (②) and lithium double-sided deposition film for anodes (③) is ongoing, with the aim of early realization.

(Figure 1)



Lithium battery structure with double-sided deposition film



Consolidated Financial Results for FY2025/6

Earnings Forecast for FY2026/6

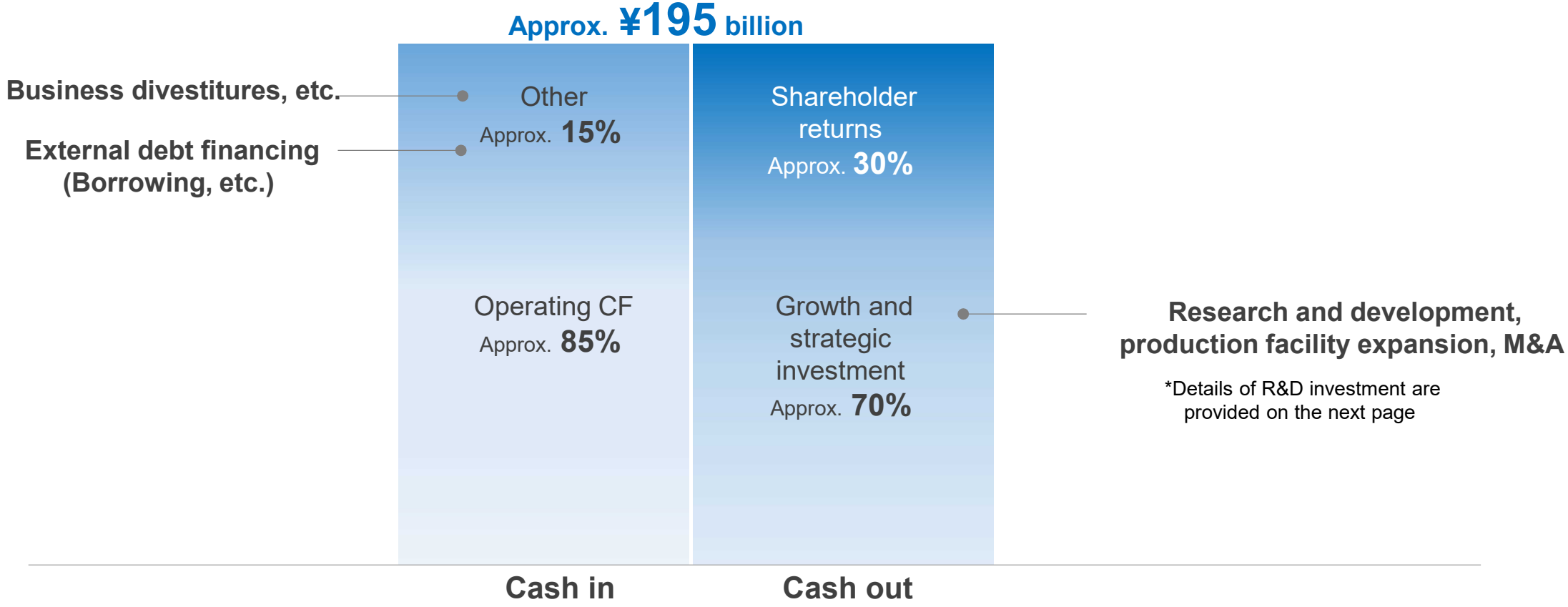
New Mid-Long-Term Management Plan
～Value Up Plan～

- Business Reforms
- Growth Strategy
- Production Reforms
- **Capital Allocation**

Capital allocation

- Focusing on semiconductor electronics, we will **strengthen research and development investments** and **implement M&A activities for growth**.
- As shareholder returns are positioned as one of the most important strategies, we aim to **enhance shareholder returns** in the future in addition to long-term increases driven by sustainable growth.

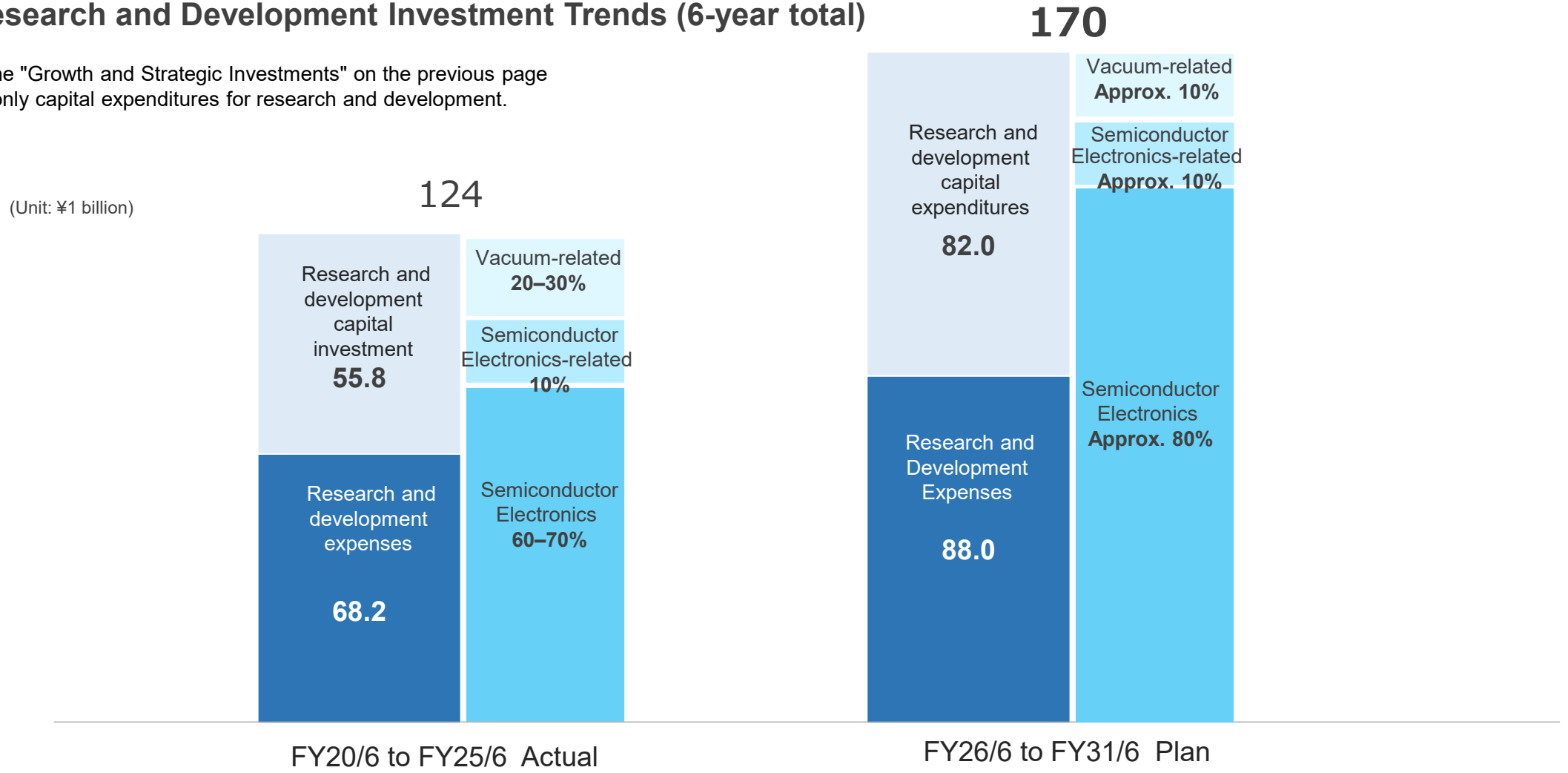
■ **Capital Allocation**
(6-year cumulative: FY2026/6–FY2031/6)



» Strengthening research and development focused on semiconductor electronics ⇒ Continuing research and development investment for further growth

■ Research and Development Investment Trends (6-year total)

*The "Growth and Strategic Investments" on the previous page only capital expenditures for research and development.

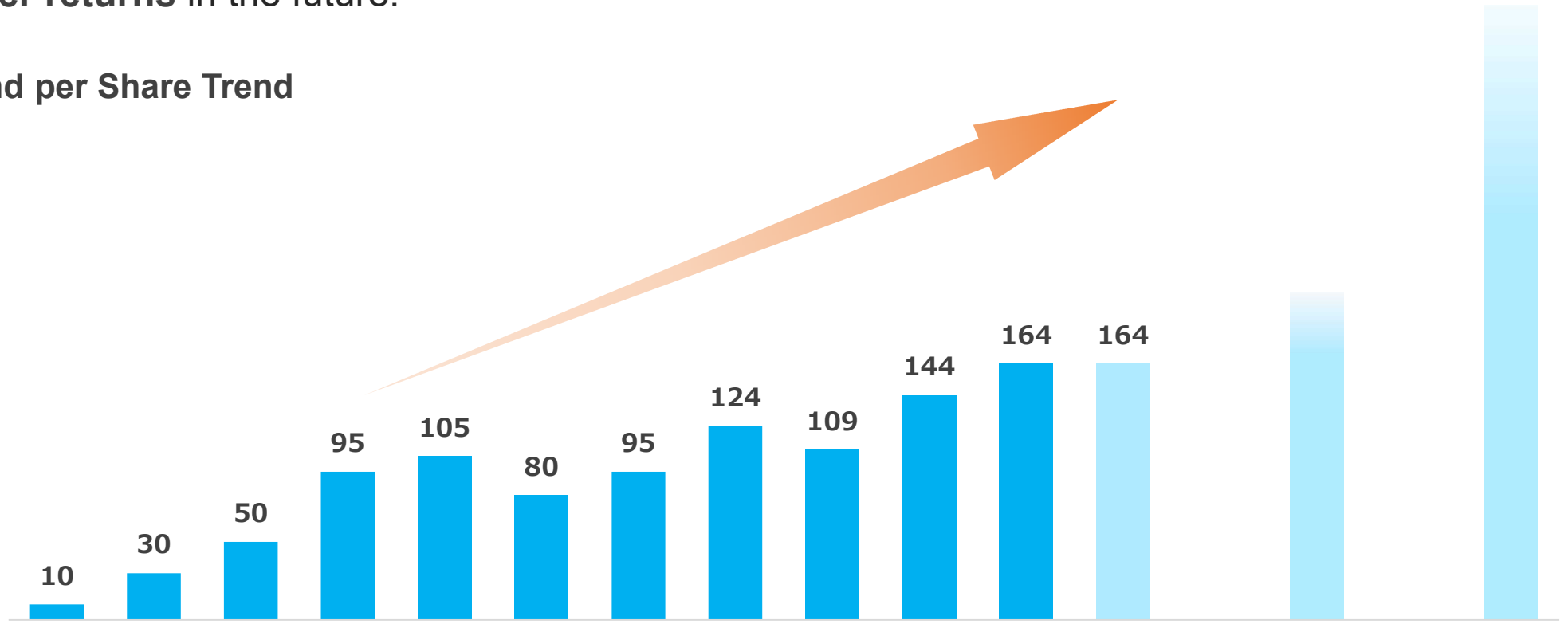


Shareholder Return Policy

- We will continue to aim for **a dividend payout ratio of 35% or higher**, and from the perspective of stable dividends prioritizing shareholder returns, we plan to pay a dividend of 164 yen per share for FY26/6, the same amount as for FY25/6.
- In addition to **long-term dividend increases** driven by sustainable growth, we aim to further **enhance shareholder returns** in the future.

■ Dividend per Share Trend

(Unit: yen)



	FY15/6	FY16/6	FY17/6	FY18/6	FY19/6	FY20/6	FY21/6	FY22/6	FY23/6	FY24/6	FY25/6	FY26/6	FY28/6	FY31/6
	Actual											Forecast	Target	Target
Dividend payout ratio(%)	5.8	8.9	10.1	13.0	27.7	36.6	31.5	30.2	37.9	35.1	35≦	35≦		

Topics

Organizational Change: New Growth & Development Division Established

Supporting the implementation of the Value-Up Plan and global strategy formulation, and the execution of growth strategies to accelerate business growth across the entire group.

CEO

- Management Planning Division
- **Growth & Development Division**
- Business Strategy Division
- Sustainable Management Division
- Security Trade Control Division
- Quality Assurance Division
- Legal Division
- Internal Auditing Division
- Administration HQ — General Administration Division, Human Resources Division, Finance & Accounting Division, IR Division, Sales Administration Division, IT Planning Promotion Division, Kyushu Factory/ Tohoku Factory(Facility Management)
- Development HQ — Advanced Technology Research Institute, Future Technology Research Institute
- Production HQ — Production Coordination Division, Procurement Division
- Semiconductor & Advanced Electronics Business HQ — Semiconductor Equipment BU, Advanced Electronics Equipment BU
- Component Business HQ — Components BU
- Materials BU
- VMS BU
- CS Business HQ

Fuji Susono Plant's electricity usage: 100% renewable energy achieved

By July 2025, the Fujisusono Plant, a major production site for semiconductor and electronic devices, will complete the transition to electricity sourced entirely from renewable energy.

Going forward, we will continue to advance the planned introduction of solar power generation facilities and promote the procurement of various renewable energy sources to contribute to the realization of a sustainable society.

Fujisono Plant

Appendix

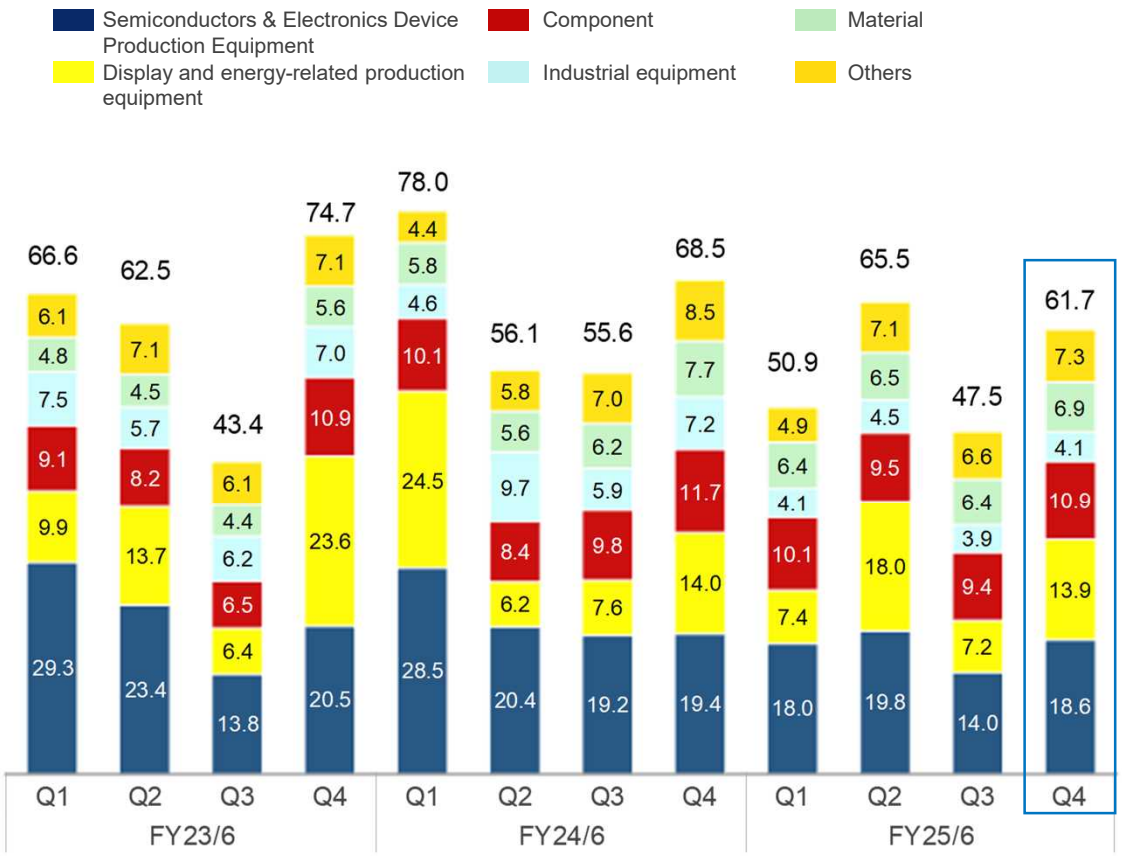
Business results (Quarterly Trends)

(Unit: ¥1 billion)	FY2024/6 Q1	Q2	Q3	Q4	Full Year	FY2025/6 Q1	Q2	Q3	Q4	Full Year
Orders Received	78.0	56.1	55.6	68.5	258.2	50.9	65.5	47.5	61.7	225.6
Net Sales	55.0	65.2	65.0	75.9	261.1	61.0	73.9	52.9	63.5	251.2
Gross Profit	15.3	20.1	22.0	23.3	80.7	19.1	23.8	17.6	19.3	79.9
Gross Profit Margin	27.7%	30.8%	33.8%	30.7%	30.9%	31.3%	32.2%	33.3%	30.5%	31.8%
SG&A	12.4	12.6	11.9	13.9	50.9	13.4	14.2	12.2	13.6	53.3
Operating Profit	2.8	7.5	10.1	9.4	29.8	5.8	9.6	5.4	5.8	26.5
Operating Profit Margin	5.1%	11.5%	15.5%	12.3%	11.4%	9.4%	13.0%	10.2%	9.1%	10.6%
Profit attributable to owners of parent	1.1	5.7	6.4	6.9	20.2	3.7	6.7	2.7	3.6	16.7
To net sales ratio	2.1%	8.8%	9.9%	9.1%	7.7%	6.1%	9.0%	5.1%	5.6%	6.6%

Sales results (Quarterly Trends)

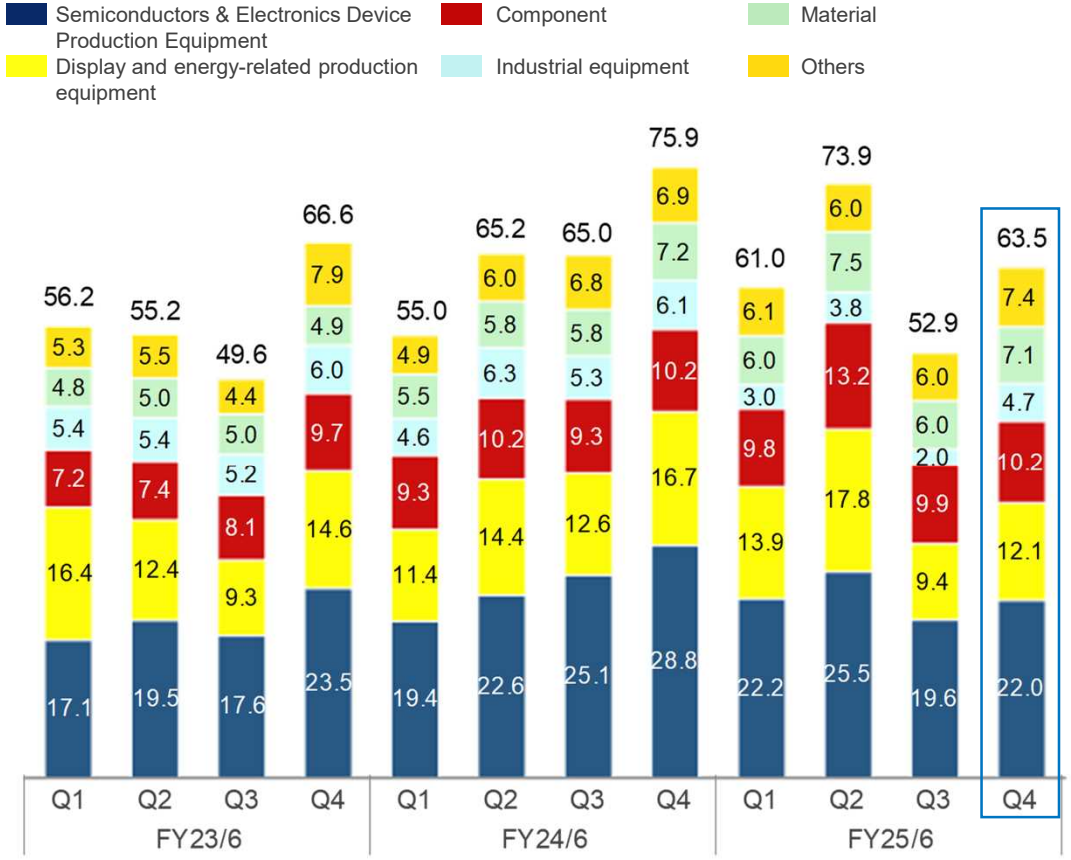
Orders Received

(Unit: ¥1 billion)



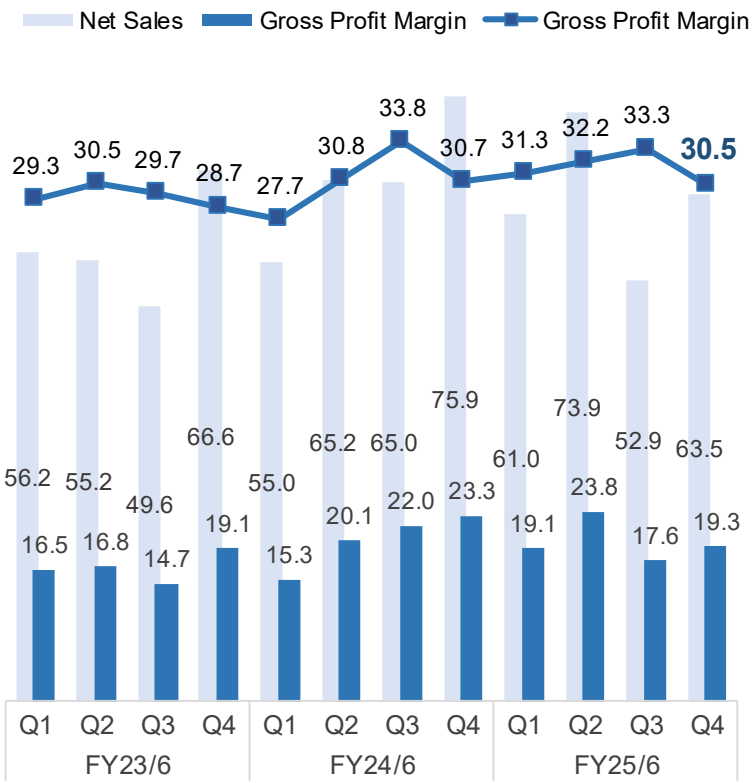
Net Sales

(Unit: ¥1 billion)

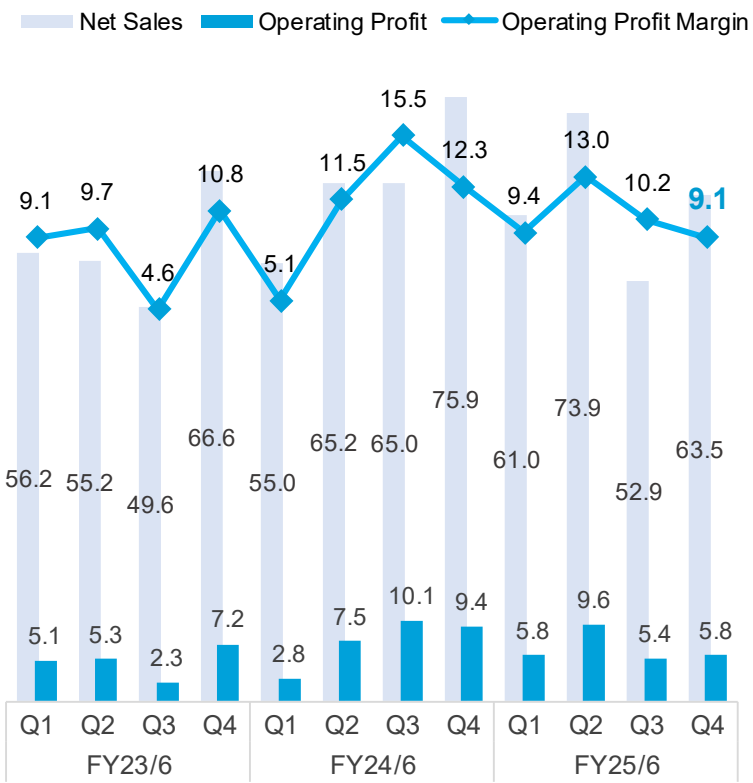


Profit margins (Quarterly Trends)

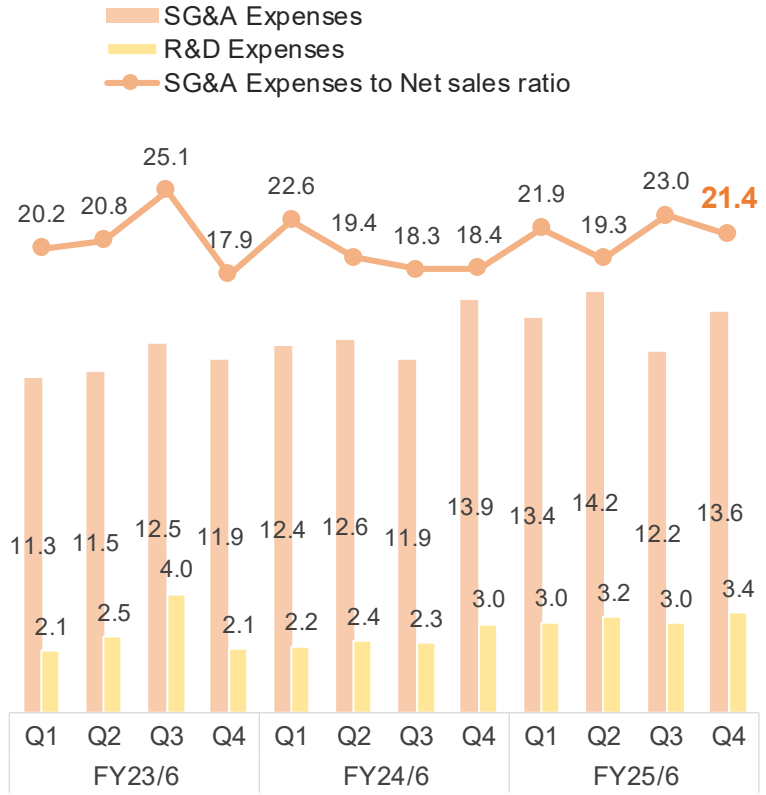
Gross profit margin (Unit: ¥ 1 billion, %)



Operating profit margin (Unit: ¥ 1 billion, %)



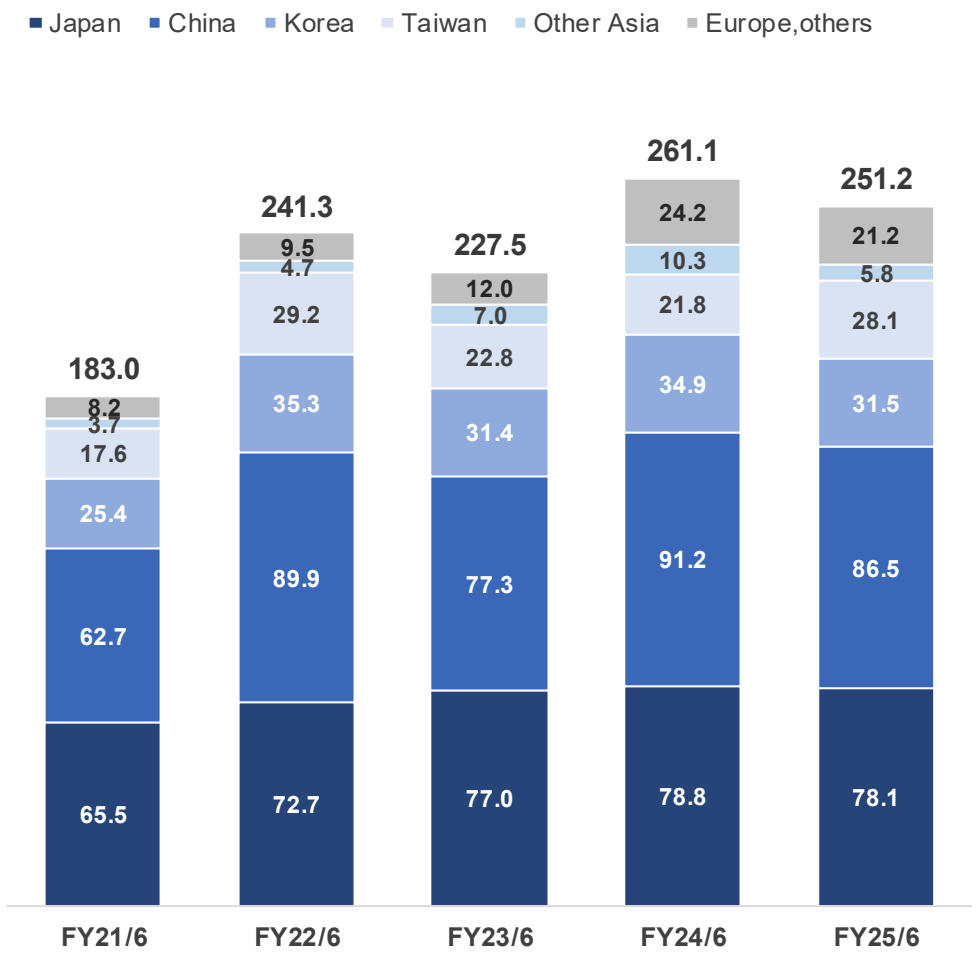
S.G.&A. Expenses(%) (Unit: ¥ 1 billion, %)



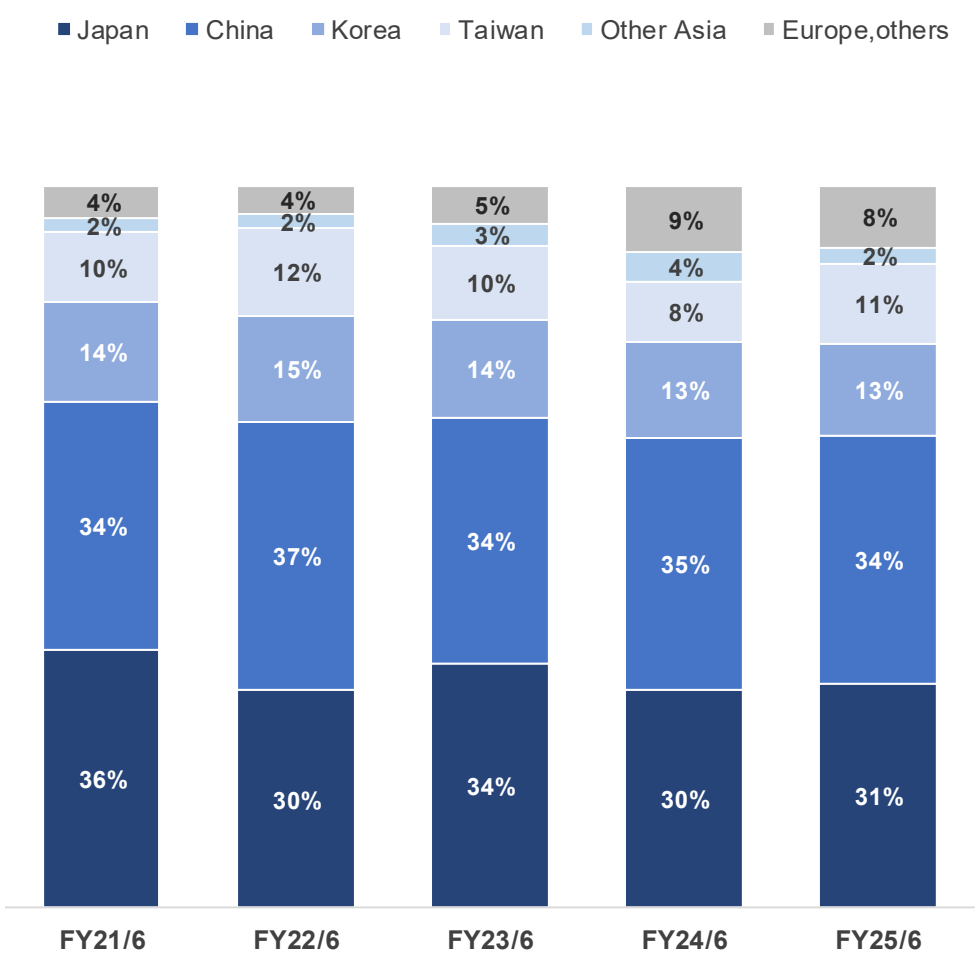
Net Sales by Region (Actual)

Net sales

(Unit: ¥1 billion)



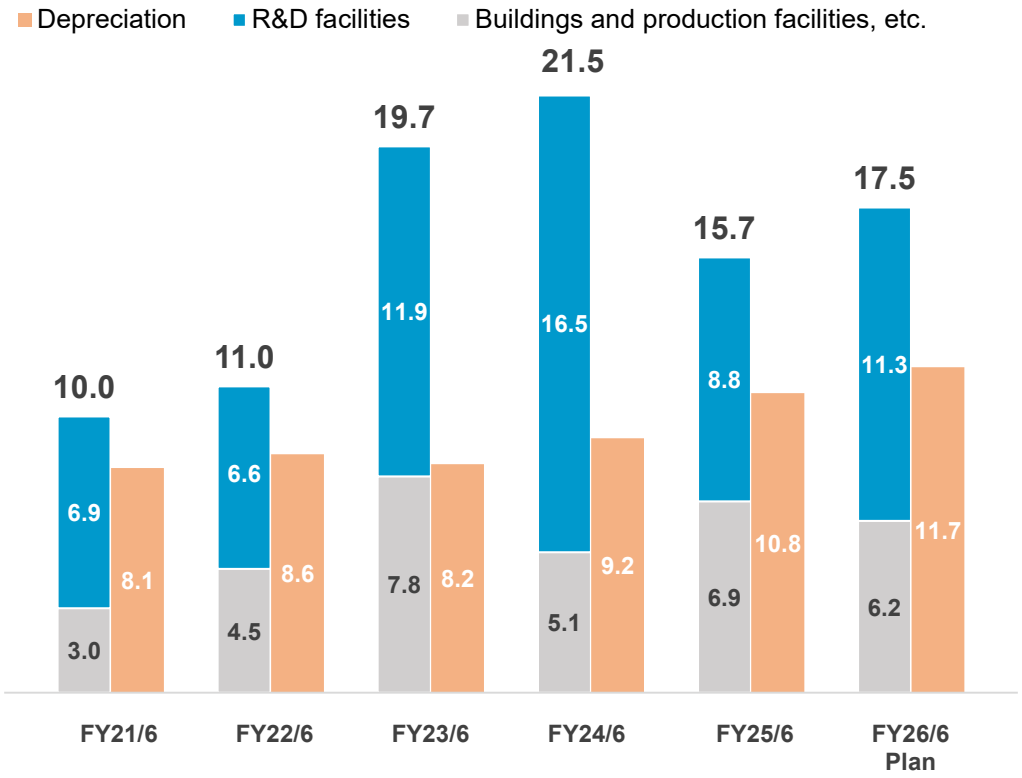
Net sales ratio



Capital Investment and R&D Expenses (Actual and FY26/6 Plan)

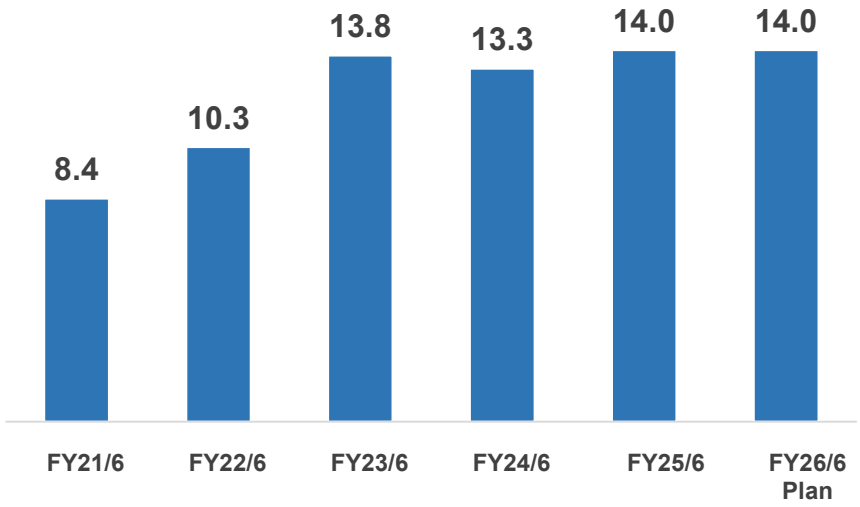
Capital Expenditures

(Unit: ￥1 billion)



R&D Expenses

(Unit: ￥1 billion)



Breakdown by Application and Operating Profit Margin Ranking

Breakdown by Application for Orders received and Net sales

Orders received	FY25/6 Actual	FY26/6 plan
Semiconductors and Electronics	**¥70.4 billion**	**¥91.0 billion**
• Memory	mid-20%	less than 30%
• Logic	mid-20%	less than 20%
• Electronics	more than 20%	more than 30%
• Power semiconductors	more than10%	more than10%
• Packaging	mid-10%	more than 10%
• Other	-	-
Display and Energy	**¥46.5 billion**	**¥40.0 billion**
• LCD	Less than 30%	about 20%
• OLEDs	less than 70%	less than 60%
• Battery	several%	about 10%
• Other	several%	more than 10%

Net sales	FY25/6 Actual	FY26/6 plan
Semiconductors and Electronics	**¥89.3 billion**	**¥100.5 billion**
• Memory	about 20%	more than 20%
• Logic	more than 20%	less than 20%
• Electronics	mid-20%	mid-30%
• Power semiconductors	mid-20%	more than 10%
• Packaging	about 10%	about 10%
• Other	-	-
Display and Energy	**¥53.1 billion**	**¥39.0 billion**
• LCD	mid-30%	less than30%
• OLEDs	mid-40%	more than 60%
• Battery	mid-10%	less than 10%
• Other	mid-single digits	several%

FY25/6 Operating profit margin ranking

Rank	Segment
1	General Industry
2	Components
3	Semiconductors and Electronics
4	Other
5	Materials
6	Display and Energy-Related

Company-wide average profit margin is between 4) Other and 5) Materials

Disclosure Document

Materials Business (Display-related)

ULVAC
(Translation)

August 13, 2025

Name of the Company:	ULVAC, Inc.
Name of the Representative:	Setsuo Iwashita President & CEO (Code No.6728; TSE Prime Market)
Person to contact:	Daichi Harada General Manager of IR Dept., Administration HQ (TEL. 0467-89-2024)

Regarding Discussions on the Integration of the FPD Target Business with KFMI

ULVAC, Inc. (President & CEO Setsuo Iwashita, hereinafter "ULVAC") and Konfoong Materials International Co., Ltd. (hereinafter "KFMI") is currently in discussions toward integrating the flat panel display (FPD) target businesses of both companies.

Please note that this integration plan is currently under investigation and consideration, and no formal agreement has been concluded at this time.

◇ Background

ULVAC develops and provides manufacturing equipment, vacuum devices, and materials for semiconductors, electronics, and FPDs, centered on vacuum technology. As announced today, we are optimizing our business structure and shifting toward the semiconductor and electronics business. Given the ongoing overseas shift of FPD manufacturing bases, we will consider developing the FPD target business in collaboration with KFMI going forward.

Pump Motors Business (China)

ULVAC
(Translation)

August 13, 2025

Name of the Company:	ULVAC, Inc.
Name of the Representative:	Setsuo Iwashita President & CEO (Code No.6728; TSE Prime Market)
Person to contact:	Daichi Harada General Manager of IR Dept., Administration HQ (TEL. 0467-89-2024)

Notice Regarding Change in Equity Ownership Ratio of ULVAC Tianma Electric (Jingjiang) Co., Ltd.

We hereby announce you that ULVAC Group and Jiangsu Shangqi Group Co., Ltd. (hereinafter "Shangqi") have entered into an equity transfer agreement.

The company supplies vacuum pump motors produced by our group on a stable basis and is positioned as an important joint venture partner in strengthening our components business. By transferring part of our equity to Shangqi, we aim to further strengthen the local production, development system and promote business growth.

◇ Equity Ownership Ratio

Party	Current	After Transfer
ULVAC Group	60%	40%
Shangqi	40%	60%

Semiconductor Glossary

PVD（Physical Vapor Deposition）
A thin-film deposition technology, primarily sputtering for ULVAC.

MHM（Metal Hard Mask）
A mask film used in etching processes for wiring layer formation.（Sputtering for ULVAC）

POR（Process of Record）
A certified process used in mass production.

HM（Hard Mask）
A mask layer formed using PVD (Physical Vapor Deposition) or similar methods.

FEOL（Front End of Line）
The initial stage of semiconductor manufacturing, forming transistors and other components on silicon wafers.

BEOL（Back End of Line）
Refers to the latter stage of the semiconductor manufacturing process, where wiring and metal layers are formed to connect devices such as transistors created during the FEOL (Front End of Line) process.

GPU（Graphics Processing Unit）
A processor designed for high-speed rendering of images and videos. It is also suitable for repetitive calculations, such as addition, subtraction, multiplication, and division, in AI inference.

HBM（High Bandwidth Memory）
A next-generation memory technology that stacks multiple DRAMs vertically for high speed and density.

WLP（Wafer Level Package）
A semiconductor packaging technology performed at the wafer level.

PLP（Panel Level Package）
A packaging technology using panel-shaped substrates instead of wafers.

ULVAC